

MOS INTEGRATED CIRCUIT

μ PD42S16800L, 42S17800L

16 M BIT DYNAMIC RAM
(3.3 V FAST PAGE MODE)

PRELIMINARY

DESCRIPTION

The NEC μ PD42S16800L and μ PD42S17800L are 2 097 152 words by 8 bits dynamic CMOS RAM with optional fast page mode. CMOS sense amplifier, peripheral circuits and 1 transistor memory cell technique realize high speed access, cycle time and low power dissipation.

Refresh is accomplished by performing $\overline{\text{RAS}}$ only refresh cycles, hidden refresh cycles, $\overline{\text{CAS}}$ before $\overline{\text{RAS}}$ refresh cycles, $\overline{\text{CAS}}$ before $\overline{\text{RAS}}$ self refresh cycles or normal read or write cycles on the 4096 address combinations of A0 to A11 (for μ PD42S16800L) or 2048 address combinations of A0 to A10 (for μ PD42S17800L) during a 256 ms period.

The μ PD42S16800L and μ PD42S17800L are packaged in 28-pin plastic SOJ and 28-pin plastic ZIP and 28-pin plastic TSOP.

FEATURES

- 2 097 152 words by 8 bits organization
- 4 performance ranges

DEVICE	ACCESS TIME (MAX.)	R/W CYCLE (MIN.)	PAGE MODE CYCLE (MIN.)	Low power dissipation	
				Active (MAX.)	Standby
μ PD42S16800L-A60	60 ns	110 ns	40 ns	288 mW	0.36 mW (MAX.) (CMOS level)
μ PD42S17800L-A60				360 mW	
μ PD42S16800L-A70	70 ns	130 ns	45 ns	252 mW	
μ PD42S17800L-A70				324 mW	
μ PD42S16800L-A80	80 ns	150 ns	50 ns	216 mW	
μ PD42S17800L-A80				288 mW	

- Single +3.3V $\pm$ 0.3V power supply
- On-chip substrate bias generator
- Multiplexed address inputs

DEVICE	Row Address	Column Address	Refresh cycle
μ PD42S16800L	A0 to A11	A0 to A8	4096 cycles/256 ms
μ PD42S17800L	A0 to A10	A0 to A9	2048 cycles/256 ms

- Non latched I/O, TTL-compatible
- Read-modify-write, Fast Page Mode capability
- $\overline{\text{RAS}}$ only refresh, hidden refresh and $\overline{\text{CAS}}$ before $\overline{\text{RAS}}$ internal address refresh
- $\overline{\text{CAS}}$ before $\overline{\text{RAS}}$ self refresh

μPD42S16800L,42S17800L

ORDERING INFORMATION

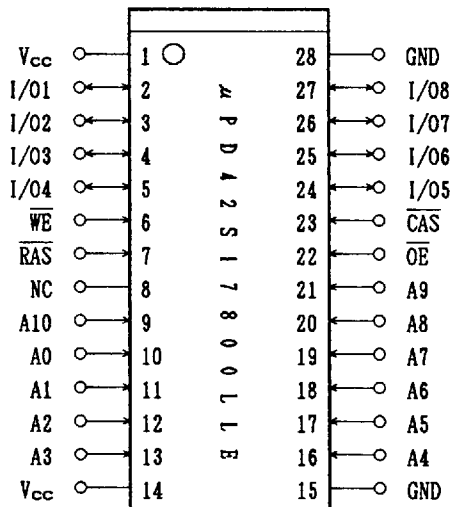
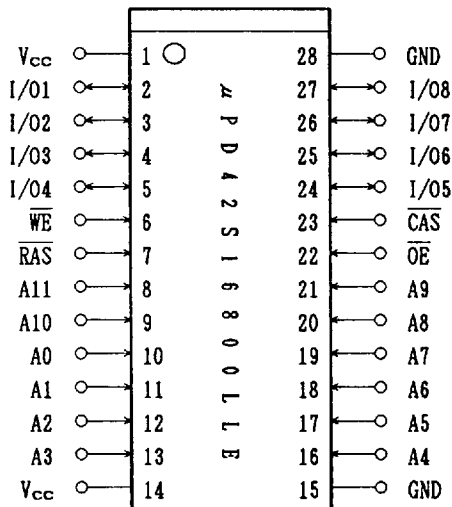
PART NUMBER	ACCESS TIME (MAX.)	PACKAGE	QUALITY GRADE
μ PD42S16800LLE-A60	60ns	28-pin Plastic SOJ	STANDARD
μ PD42S17800LLE-A60			
μ PD42S16800LLE-A70	70ns		
μ PD42S17800LLE-A70			
μ PD42S16800LLE-A80	80ns		
μ PD42S17800LLE-A80			
μ PD42S16800LV-A60	60ns	28-pin Plastic ZIP (under development)	
μ PD42S17800LV-A60			
μ PD42S16800LV-A70	70ns		
μ PD42S17800LV-A70			
μ PD42S16800LV-A80	80ns		
μ PD42S17800LV-A80			
μ PD42S16800LG5-A60-7JD	60ns	28-pin Plastic TSOP	
μ PD42S17800LG5-A60-7JD			
μ PD42S16800LG5-A70-7JD	70ns		
μ PD42S17800LG5-A70-7JD			
μ PD42S16800LG5-A80-7JD	80ns		
μ PD42S17800LG5-A80-7JD			
μ PD42S16800LG5-A60-7KD	60ns	28-pin Plastic TSOP (Reverse bent)	
μ PD42S17800LG5-A60-7KD			
μ PD42S16800LG5-A70-7KD	70ns		
μ PD42S17800LG5-A70-7KD			
μ PD42S16800LG5-A80-7KD	80ns		
μ PD42S17800LG5-A80-7KD			

Please refer to "Quality grade on NEC Semiconductor Devices" (Document number 1E1-1209) published by NEC Corporation to know the specification of quality grade on the devices and its recommended applications.

PIN CONFIGURATION (Marking Side)

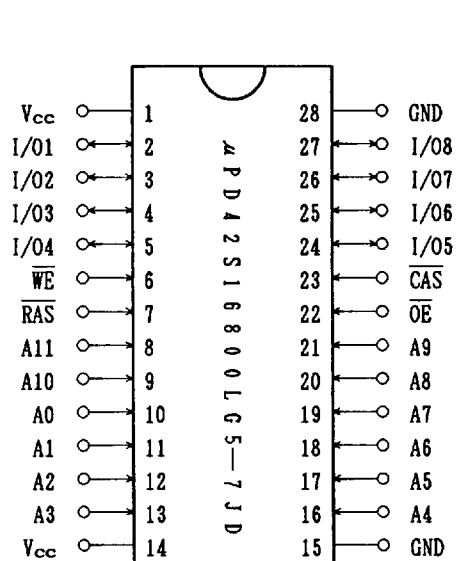
A0 to A10 (A11) : Address Inputs
 I/O1 to I/O8 : Data Inputs/Outputs
 RAS : Row Address Strobe
 CAS : Column Address Strobe
 WE : Write Enable
 OE : Output Enable
 V_{cc} : Supply Voltage
 GND : Ground
 NC : No Connection

28-pin Plastic SOJ (400 mil)

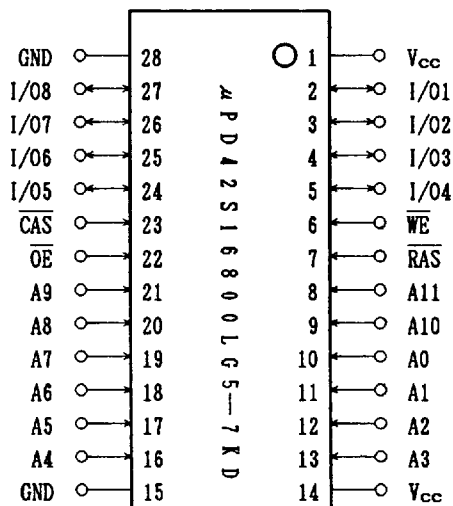


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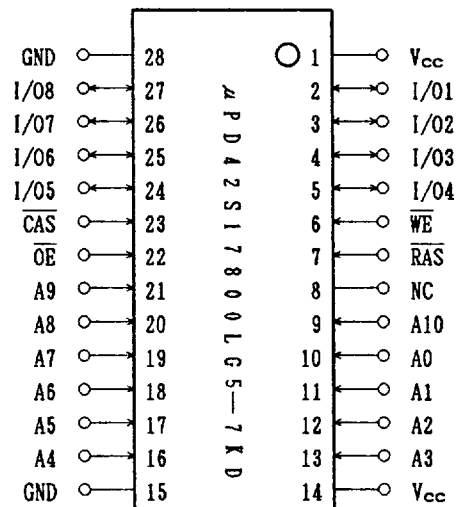
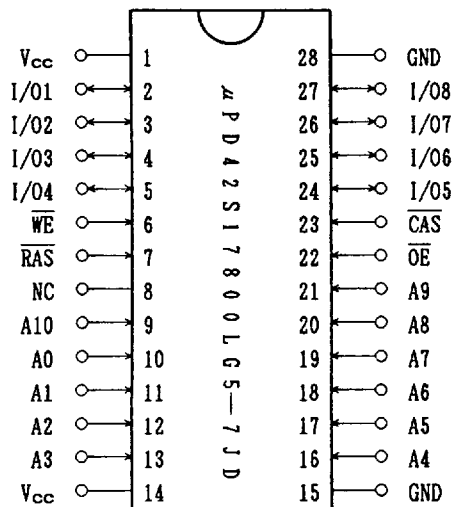
28-pin Plastic TSOP (400 mil)



Reverse bent

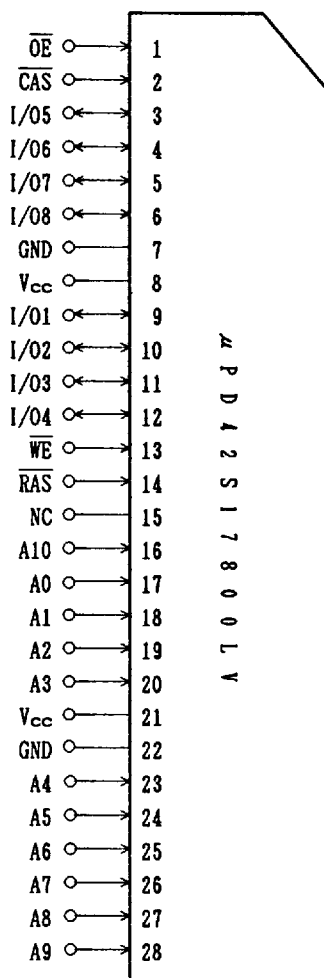
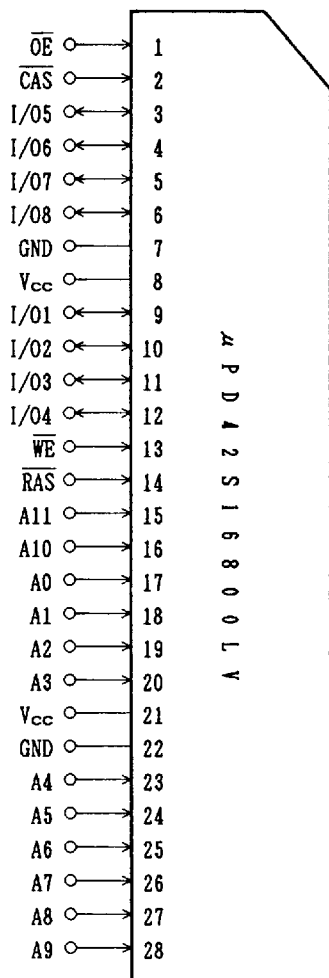


Reverse bent



μPD42S16800L,42S17800L

28-pin Plastic ZIP (475 mil)



μPD42S16800L,42S17800L

ELECTRICAL SPECIFICATIONS

ABSOLUTE MAXIMUM RATINGS*

PARAMETER	SYMBOL	TEST CONDITION	RATING	UNIT
Voltage on Any Pin Relative to GND	V_T		-0.5 to +4.6	V
Short Circuit Output Current	I_O		20	mA
Power Dissipation	P_D		1	W
Operating Temperature	T_{opt}		0 to 70	°C
Storage Temperature	T_{stg}		-55 to +125	°C

*COMMENT : Exposing the device to stress above those listed in Absolute Maximum Ratings could cause permanent damage. The device is not meant to be operated under conditions outside the limits described in the operational sections of this specification. Exposure to Absolute Maximum Rating conditions for extended periods may affect device reliability.

RECOMMENDED OPERATING CONDITIONS NOTES:1,2

PARAMETER	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Supply Voltage	V_{CC}		3.0	3.3	3.6	V
High Level Input Voltage	V_{IH}		2.0		$V_{CC}+0.3$	V
Low Level Input Voltage	V_{IL}		-0.3		0.8	V
Ambient Temperature	T_a		0		70	°C

CAPACITANCE ($T_a=25^{\circ}C$, $f=1$ MHz)

PARAMETER	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Input Capacitance	C_{I1}	A0 to A10(A11)			5	pF
	C_{I2}	$\overline{RAS}$, $\overline{CAS}$, $\overline{WE}$, $\overline{OE}$			7	pF
Data Input/Output Capacitance	C_D	I/O1 to I/O8			7	pF

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DC CHARACTERISTICS (Recommended Operating Conditions unless Otherwise noted)

【μPD42S16800L】

PARAMETER	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT	NOTES
Operating Current	I _{CC1}	RAS, CAS Cycling t _{RC} =t _{RC(MIN.)} , I _O =0mA	μPD42S16800L-A60		80	mA	3
			μPD42S16800L-A70		70		
			μPD42S16800L-A80		60		
Standby Current	I _{CC2}	RAS, CAS ≥ V _{IH(MIN.)} , I _O =0mA			0.5	mA	
		RAS, CAS ≥ V _{CC} -0.2V, I _O =0mA			0.1		
Refresh Current (RAS Only Refresh)	I _{CC3}	RAS Cycling, CAS ≥ V _{IH(MIN.)} t _{RC} =t _{RC(MIN.)} , I _O =0mA	μPD42S16800L-A60		80	mA	3
			μPD42S16800L-A70		70		
			μPD42S16800L-A80		60		
Operating Current (Fast Page Mode)	I _{CC4}	CAS Cycling, RAS ≤ V _{IL(MAX.)} t _{PC} =t _{PC(MIN.)} , I _O =0mA	μPD42S16800L-A60		70	mA	3
			μPD42S16800L-A70		60		
			μPD42S16800L-A80		50		
Refresh Current (CAS before RAS Refresh)	I _{CC5}	RAS Cycling, t _{RC} =t _{RC(MIN.)} , I _O =0mA	μPD42S16800L-A60		80	mA	3
			μPD42S16800L-A70		70		
			μPD42S16800L-A80		60		
Battery back-up Current (Standby with CAS before RAS Refresh)	I _{CC6}	Standby: V _{CC} -0.2V ≤ RAS, CAS before RAS Refresh: 4096 Cycle/256 ms RAS, CAS: 0V ≤ V _{IL} ≤ 0.2V V _{CC} -0.2V ≤ V _{IH} ≤ V _{IH MAX.} WE, OE: V _{IH} Address: Don't care Output: OPEN	t _{RAS} ≤ 300ns		140	μA	
			t _{RAS} ≤ 1μs		140		
Self Refresh Current (CAS before RAS Self Refresh)	I _{CC7}	RAS, CAS: 0V ≤ V _{IL} ≤ 0.2V V _{CC} -0.2V ≤ V _{IH} ≤ V _{IH MAX.} I _O =0mA			80	μA	
Input Leakage Current	I _{I(L)}	V _I =0 to 3.6V, all other pins= 0V	-5		5	μA	
Output Leakage Current	I _{O(L)}	D _{OUT} is disabled, V _O =0 to 3.6V	-5		5	μA	
Output High Voltage	V _{OH}	I _O =-2mA	2.4			V	
Output Low Voltage	V _{OL}	I _O =2mA			0.4	V	

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【μPD42S17800L】

PARAMETER	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT	NOTES
Operating Current	I _{CC1}	RAS, CAS Cycling t _{RC} =t _{RC(MIN.)} , I _O =0mA	μPD42S17800L-A60		100	mA	3
			μPD42S17800L-A70		90		
			μPD42S17800L-A80		80		
Standby Current	I _{CC2}	RAS, CAS ≥ V _{IH(MIN.)} , I _O =0mA			0.5	mA	
		RAS, CAS ≥ V _{CC} -0.2V, I _O =0mA			0.1		
Refresh Current (RAS Only Refresh)	I _{CC3}	RAS Cycling, CAS ≥ V _{IH(MIN.)} t _{RC} =t _{RC(MIN.)} , I _O =0mA	μPD42S17800L-A60		100	mA	3
			μPD42S17800L-A70		90		
			μPD42S17800L-A80		80		
Operating Current (Fast Page Mode)	I _{CC4}	CAS Cycling, RAS ≤ V _{IL(MAX.)} t _{PC} =t _{PC(MIN.)} , I _O =0mA	μPD42S17800L-A60		70	mA	3
			μPD42S17800L-A70		60		
			μPD42S17800L-A80		50		
Refresh Current (CAS before RAS Refresh)	I _{CC5}	RAS Cycling, t _{RC} =t _{RC(MIN.)} , I _O =0mA	μPD42S17800L-A60		100	mA	3
			μPD42S17800L-A70		90		
			μPD42S17800L-A80		80		
Battery back-up Current (Standby with CAS before RAS Refresh)	I _{CC6}	Standby: V _{CC} -0.2V ≤ RAS, CAS before RAS Refresh: 4096 Cycle/256 ms RAS, CAS: 0V ≤ V _{IL} ≤ 0.2V V _{CC} -0.2V ≤ V _{IH} ≤ V _{IH MAX.} WE, OE: V _{IH} Address: Don't care Output: OPEN	t _{RAS} ≤ 300ns		120	μA	
			t _{RAS} ≤ 1μs		120		
Self Refresh Current (CAS before RAS Self Refresh)	I _{CC7}	RAS, CAS: 0V ≤ V _{IL} ≤ 0.2V V _{CC} -0.2V ≤ V _{IH} ≤ V _{IH MAX.} I _O =0mA			80	μA	
Input Leakage Current	I _{I(L)}	V _I =0 to 3.6V, all other pins= 0V	-5		5	μA	
Output Leakage Current	I _{O(L)}	D _{OUT} is disabled, V _O =0 to 3.6V	-5		5	μA	
Output High Voltage	V _{OH}	I _O =-2mA	2.4			V	
Output Low Voltage	V _{OL}	I _O =2mA			0.4	V	

μPD42S16800L,42S17800L

AC CHARACTERISTICS

(Recommended Operating Conditions unless Otherwise noted) NOTES: 2,4,5

(1/2)

PARAMETER	SYMBOL	μ PD42S16800L-A60 μ PD42S17800L-A60		μ PD42S16800L-A70 μ PD42S17800L-A70		μ PD42S16800L-A80 μ PD42S17800L-A80		UNIT	NOTES
		MIN.	MAX.	MIN.	MAX.	MIN.	MAX.		
Random Read or Write Cycle Time	t _{RC}	110		130		150		ns	6
Read Write Cycle Time	t _{RWC}	160		180		200		ns	6
Fast Page Mode Cycle Time(Read or Write)	t _{PC}	40		45		50		ns	6
Read Modify Write Cycle Time(Fast Page Mode)	t _{PRWC}	85		90		100		ns	6
Access Time from $\overline{\text{RAS}}$	t _{RAC}		60		70		80	ns	7, 8
Access Time from $\overline{\text{CAS}}$ (Falling Edge)	t _{CAC}		15		18		20	ns	7, 8
Access Time from Column Address	t _{AA}		30		35		40	ns	7, 8
Access Time from $\overline{\text{CAS}}$ Precharge	t _{ACP}		35		40		45	ns	7
Access Time from $\overline{\text{OE}}$	t _{OEA}		15		18		20	ns	
$\overline{\text{RAS}}$ to Column Address Delay Time	t _{RAD}	15	30	15	35	17	40	ns	8
$\overline{\text{CAS}}$ -Data Set-up Time	t _{CLZ}	0		0		0		ns	7
$\overline{\text{OE}}$ -Data Set-up Time	t _{OLZ}	0		0		0		ns	7
Output Buffer Turn-off Delay ($\overline{\text{CAS}}$)	t _{OPF}	0	13	0	15	0	15	ns	9
$\overline{\text{OE}}$ Data Delay Time	t _{ORD}	13		15		15		ns	
Output Buffer Turn-off Delay ($\overline{\text{OE}}$)	t _{OEZ}	0	13	0	15	0	15	ns	9
$\overline{\text{OE}}$ Command Hold Time	t _{OBH}	0		0		0		ns	
$\overline{\text{OE}}$ to $\overline{\text{RAS}}$ inactive Set-up Time	t _{OES}	0		0		0		ns	
Transition Time (Rise and Fall)	t _T	3	50	3	50	3	50	ns	
$\overline{\text{RAS}}$ Precharge Time	t _{RP}	40		50		60		ns	
$\overline{\text{RAS}}$ Pulse Width (Random Read,Write Cycle)	t _{RAS}	60	10000	70	10000	80	10000	ns	
$\overline{\text{RAS}}$ Pulse Width (Fast Page Mode)	t _{RASP}	60	125000	70	125000	80	125000	ns	
$\overline{\text{RAS}}$ Hold Time	t _{RSH}	15		18		20		ns	
$\overline{\text{CAS}}$ Pulse Width	t _{CAS}	15	10000	18	10000	20	10000	ns	
$\overline{\text{CAS}}$ Hold Time	t _{CSH}	60		70		80		ns	
$\overline{\text{RAS}}$ to $\overline{\text{CAS}}$ Delay Time	t _{RCD}	20	45	20	50	25	60	ns	8
$\overline{\text{CAS}}$ to $\overline{\text{RAS}}$ Precharge Time	t _{CRP}	5		5		5		ns	10
$\overline{\text{CAS}}$ Precharge Time	t _{CPN}	10		10		10		ns	
$\overline{\text{CAS}}$ Precharge Time (Fast Page Mode)	t _{CP}	10		10		10		ns	
$\overline{\text{RAS}}$ Precharge $\overline{\text{CAS}}$ Hold Time	t _{RPC}	5		5		5		ns	
$\overline{\text{RAS}}$ Hold Time from $\overline{\text{CAS}}$ Precharge	t _{RHCP}	35		40		45		ns	
Row Address Set-up Time	t _{ASR}	0		0		0		ns	
Row Address Hold Time	t _{RAH}	10		10		12		ns	

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(2/2)

PARAMETER	SYMBOL	μPD42S16800L-A60 μPD42S17800L-A60	μPD42S16800L-A70 μPD42S17800L-A70	μPD42S16800L-A80 μPD42S17800L-A80	UNIT	NOTES
		MIN.	MAX.	MIN.	MAX.	
Column Address Set-up Time	t _{ASC}	0		0		ns
Column Address Hold Time	t _{CAH}	15		15		ns
Column Address Lead Time Referenced to $\overline{\text{RAS}}$	t _{RAL}	30		35		ns
Read Command Set-up Time	t _{RCS}	0		0		ns
Read Command Hold Time Referenced to $\overline{\text{RAS}}$	t _{RRH}	0		0		ns 11
Read Command Hold Time Referenced to $\overline{\text{CAS}}$	t _{RCH}	0		0		ns 11
Write Command Hold Time Referenced to $\overline{\text{CAS}}$	t _{WCH}	10		10	15	ns 12
Write Command Pulse Width	t _{WP}	10		10	15	ns 12
Data-in Set-up Time	t _{DS}	0		0		ns 13
Data-in Hold Time	t _{DH}	10		15	15	ns 13
$\overline{\text{WE}}$ Command Set-up Time	t _{WCS}	0		0		ns 14
CAS to $\overline{\text{WE}}$ Delay	t _{CWD}	38		43	45	ns 15
$\overline{\text{RAS}}$ to $\overline{\text{WE}}$ Delay	t _{RWD}	83		95	105	ns 15
Column Address to $\overline{\text{WE}}$ Delay Time	t _{AWD}	53		60	65	ns 15
Write Command to $\overline{\text{RAS}}$ Lead Time	t _{RWL}	20		20	20	ns
Write Command to $\overline{\text{CAS}}$ Lead Time	t _{CWL}	15		15	15	ns
$\overline{\text{CAS}}$ Set-up Time for CBR Refresh	t _{CSR}	5		5	5	ns
$\overline{\text{CAS}}$ Hold Time for CBR Refresh	t _{CHR}	10		10	10	ns
$\overline{\text{RAS}}$ Pulse Width (Self Refresh Cycle)	t _{RASS}	100		100	100	μs
$\overline{\text{RAS}}$ Precharge Time (Self Refresh Cycle)	t _{RPS}	110		130	150	ns
$\overline{\text{CAS}}$ Hold Time (Self Refresh Cycle)	t _{CHS}	-50		-50	-50	ns
$\overline{\text{WE}}$ Set-up Time	t _{WSR}	10		10	10	ns
$\overline{\text{WE}}$ Hold Time	t _{WHR}	15		15	15	ns
Refresh Period	t _{REF}		256		256	ms 16

NOTES:

1. All voltages referenced to GND.
2. An initial pause of 100 μs required after power-on followed by 8 refresh ($\overline{\text{RAS}}$ only refresh or $\overline{\text{CAS}}$ before $\overline{\text{RAS}}$ refresh) cycles before proper device operation is achieved.
3. I_{CC1} , I_{CC3} , I_{CC4} and I_{CC5} depend on output loading and cycle rates. Specified values are obtained with the output open. In addition to this, I_{CC3} is measured on condition that column addresses in $\overline{\text{RAS}}$ only cycle are held high or low level and I_{CC4} is measured on condition that column addresses in fast page mode are changed only one time during $t_{PC}(\text{MIN.})$.
4. AC measurements assume $t_T=5\text{ns}$
5. $V_{IH}(\text{MIN.})$ and $V_{IL}(\text{MAX.})$ are reference levels for measuring timing of input signals. Transition times are measured between V_{IH} and V_{IL} .
6. The minimum specifications are used only to indicate cycle time at which proper operation over the full temperature range ($T_a=0$ to 70°C) is assured.
7. Load = 1 TTL loads and 100pF ($V_{OH}=2.0\text{V}$, $V_{OL}=0.8\text{V}$)
8. The access time is determined by $\overline{\text{RAS}}$ access time t_{RAC} , address access time t_{AA} , and $\overline{\text{CAS}}$ address time t_{CAC} . The relationship between these access time and t_{RCD} , t_{RAD} is as follows.

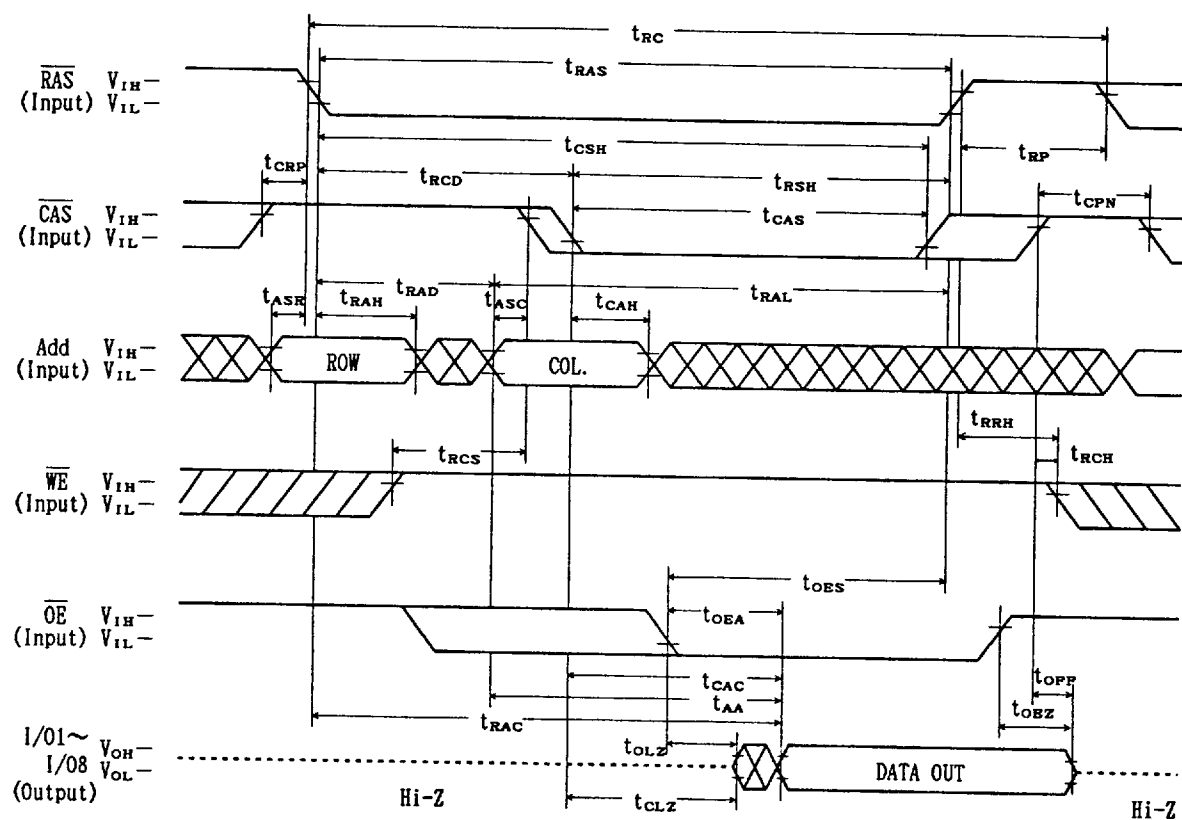
CONDITION	ACCESS TIME
$t_{RAD} \leq t_{RAD}(\text{MAX.})$ and $t_{RCD} \leq t_{RCD}(\text{MAX.})$	$t_{RAC}(\text{MAX.})$
$t_{RAD} \geq t_{RAD}(\text{MAX.})$	$t_{AA}(\text{MAX.})$
$t_{RCD} \geq t_{RCD}(\text{MAX.})$	$t_{CAC}(\text{MAX.})$

9. $t_{OFF}(\text{MAX.})$ and $t_{OBZ}(\text{MAX.})$ defines the time at which the output achieves the open circuit condition and is not referenced to V_{OH} or V_{OL} .
10. t_{CRP} requirement should be applicable for $\overline{\text{RAS}}/\overline{\text{CAS}}$ cycles preceded by any cycles.
11. Either t_{RRH} or t_{RCH} must be satisfied for a read cycle.
12. t_{WP} is applicable for late write cycle. If the cycle is early write, it should be satisfied value of t_{WCH} .
13. These parameters are referenced to $\overline{\text{CAS}}$ leading edge in early write cycles and to $\overline{\text{WE}}$ leading edge in late write or read-modify-write cycles.
14. If $t_{WCS} \geq t_{WCS}(\text{MIN.})$ the cycle is an early write cycle and the data output will remain open circuit throughout the entire cycle.
15. If $t_{CWD} \geq t_{CWD}(\text{MIN.})$, $t_{RWD} \geq t_{RWD}(\text{MIN.})$, $t_{AWD} \geq t_{AWD}(\text{MIN.})$ the cycle is a read-write and the data output will contain data read from the selected cell. If neither of the above conditions are met, the condition of the data out (at access time and until $\overline{\text{CAS}}$ goes back to V_{IH}) is indeterminate.
16. How to enter into $\overline{\text{CAS}}$ before $\overline{\text{RAS}}$ self refresh mode.
 - In case of using distributed $\overline{\text{CAS}}$ before $\overline{\text{RAS}}$ refresh
Refresh 2048 or 4096 times during a 256ms (Before set into the $\overline{\text{CAS}}$ before $\overline{\text{RAS}}$ self refresh mode, and after reset).
 - In case of using burst $\overline{\text{CAS}}$ before $\overline{\text{RAS}}$ refresh
Refresh 2048 times during a 32ms (μPD42S17800L) or 4096 times during a 64ms (μPD42S16800L) (Before set into the $\overline{\text{CAS}}$ before $\overline{\text{RAS}}$ self refresh mode, and after reset).
 - In case of use $\overline{\text{RAS}}$ only refresh
Refresh against all refresh address during 32ms (μPD42S17800L) or 64ms (μPD42S16800L) (Before set into the $\overline{\text{CAS}}$ before $\overline{\text{RAS}}$ self refresh mode, and after reset).

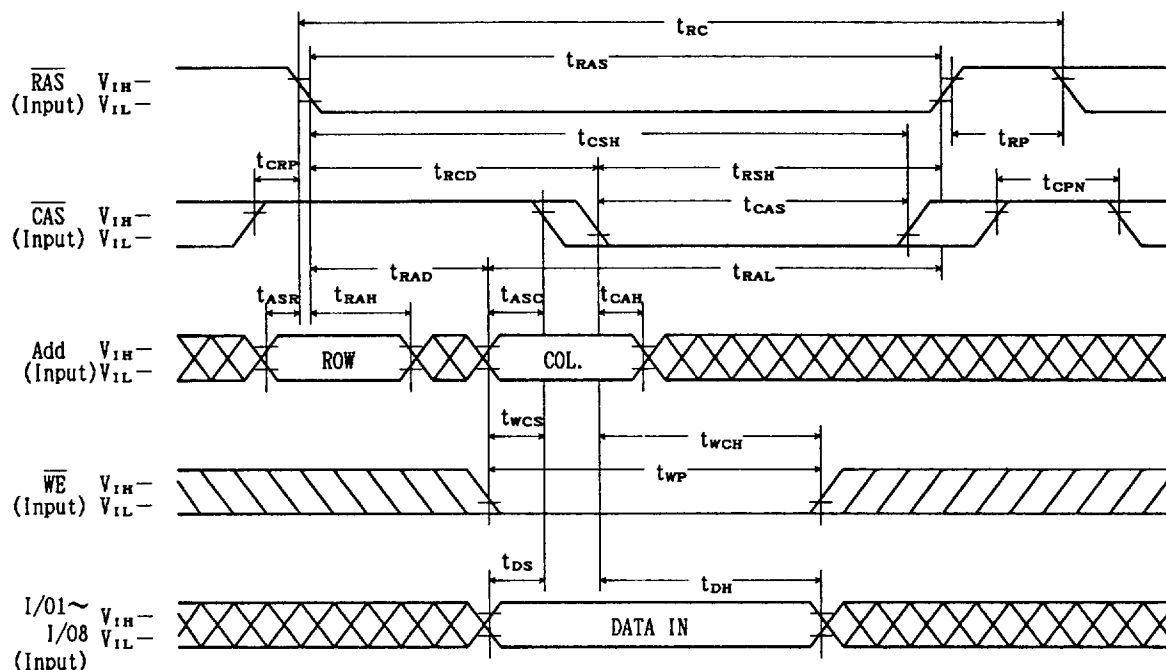
μ PD42S16800L, 42S17800L

TIMING DIAGRAMS

READ CYCLE

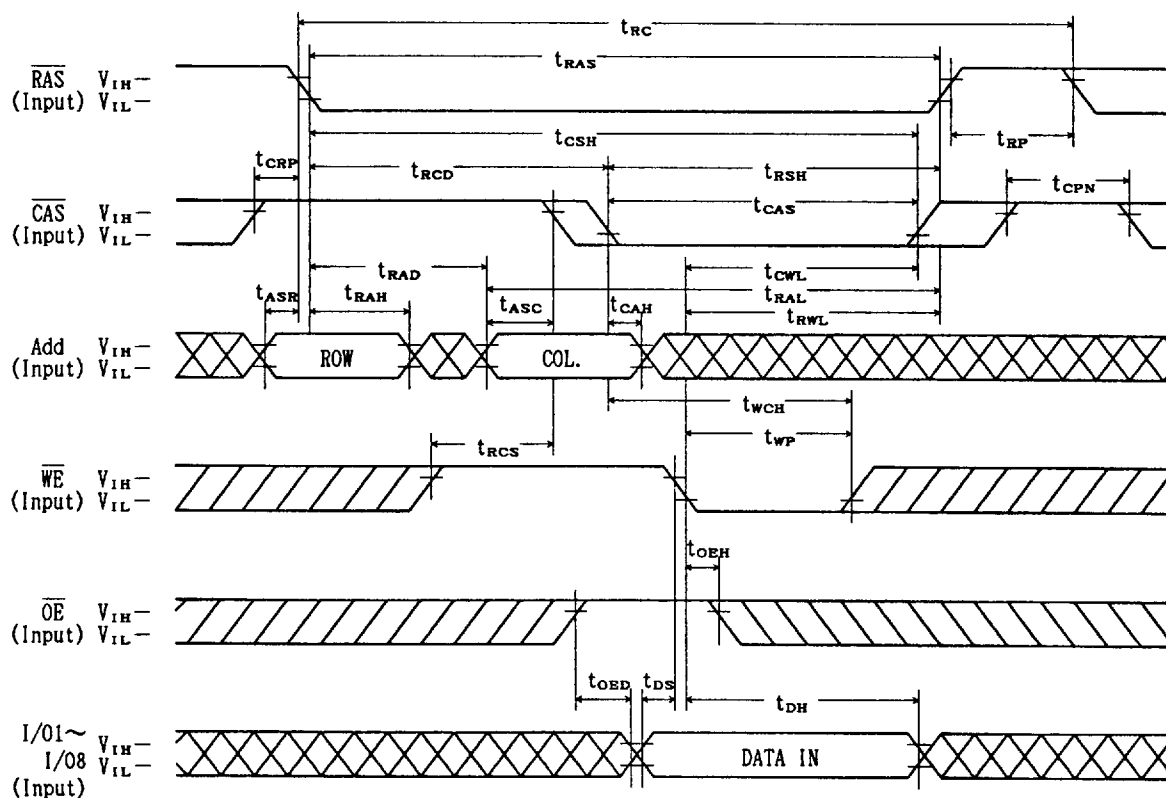


EARLY WRITE CYCLE



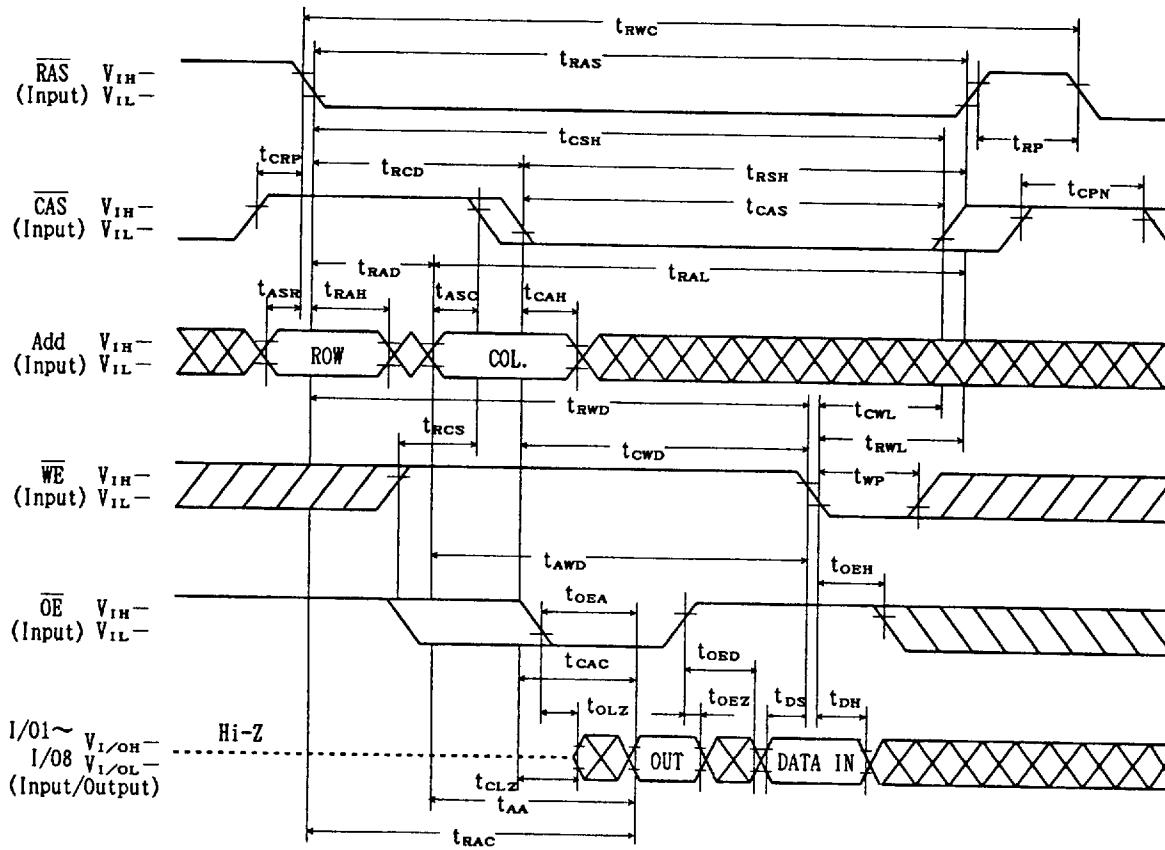
Note: $\overline{OE}$ = Don't care

LATE WRITE CYCLE

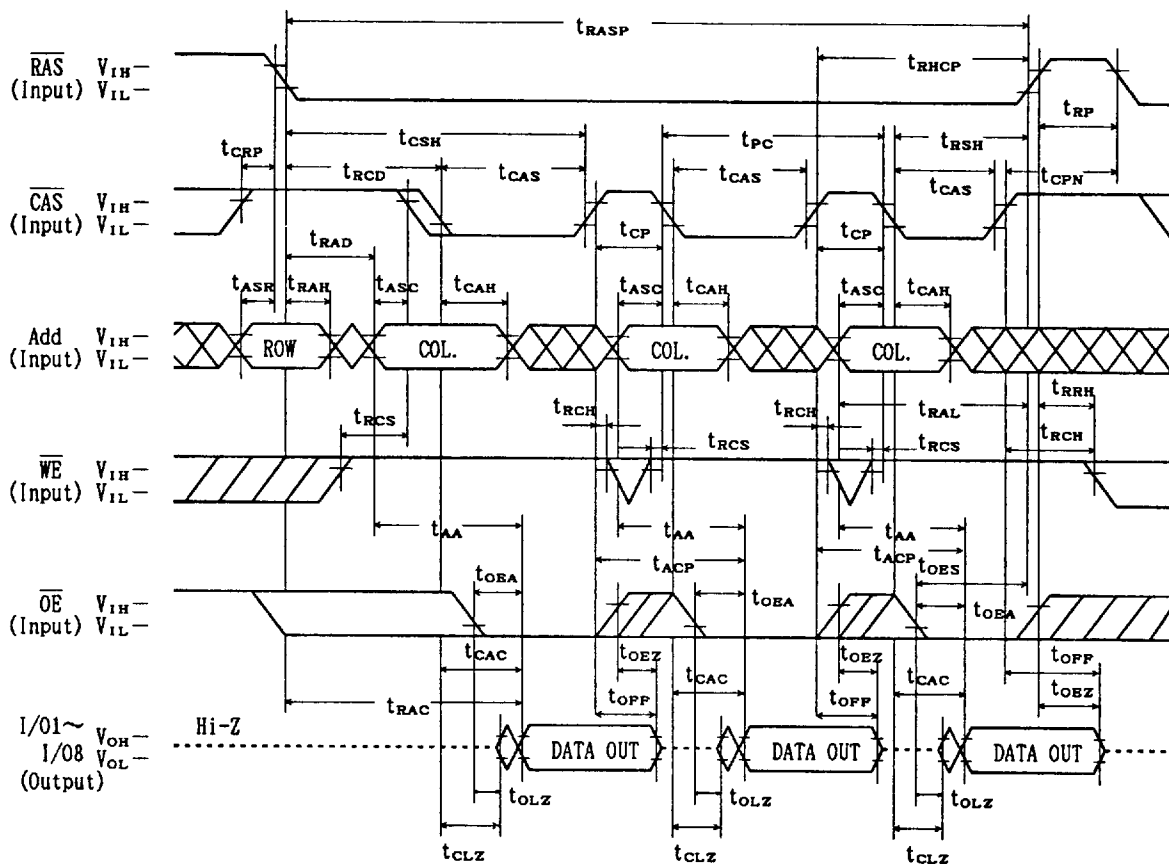


μ PD42S16800L, 42S17800L

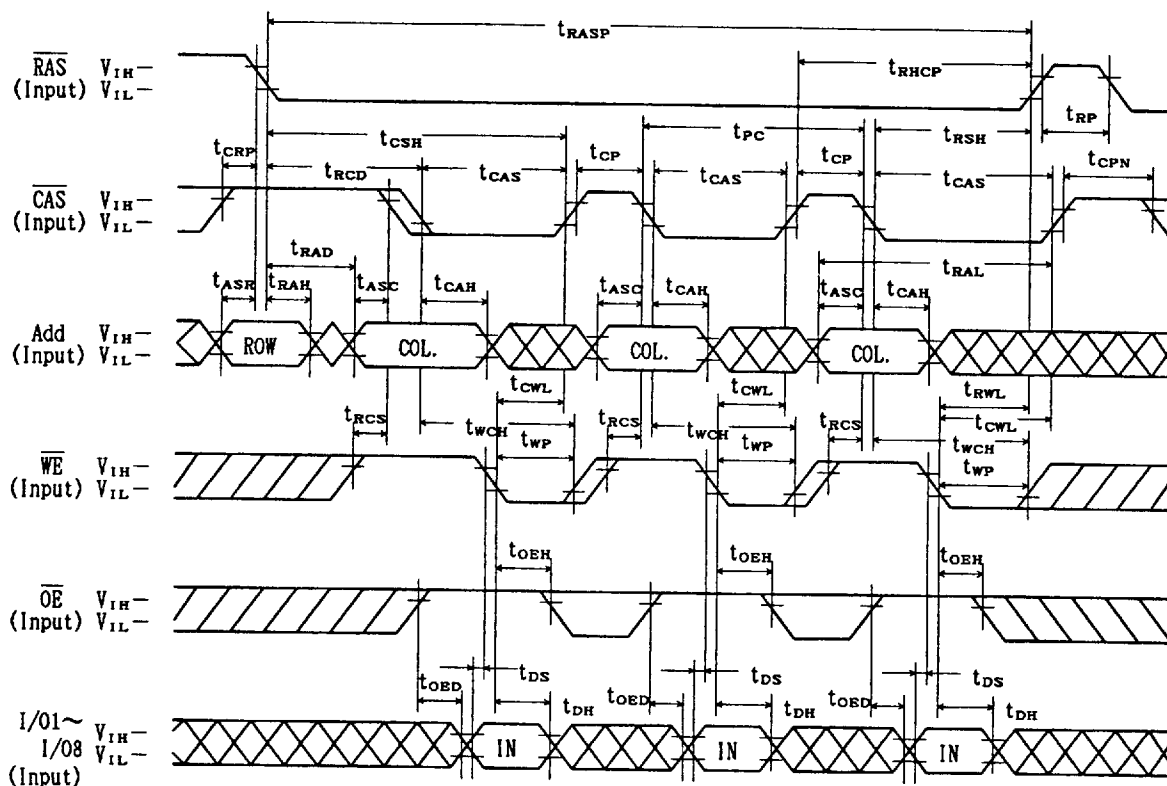
READ MODIFY WRITE CYCLE



FAST PAGE MODE READ CYCLE



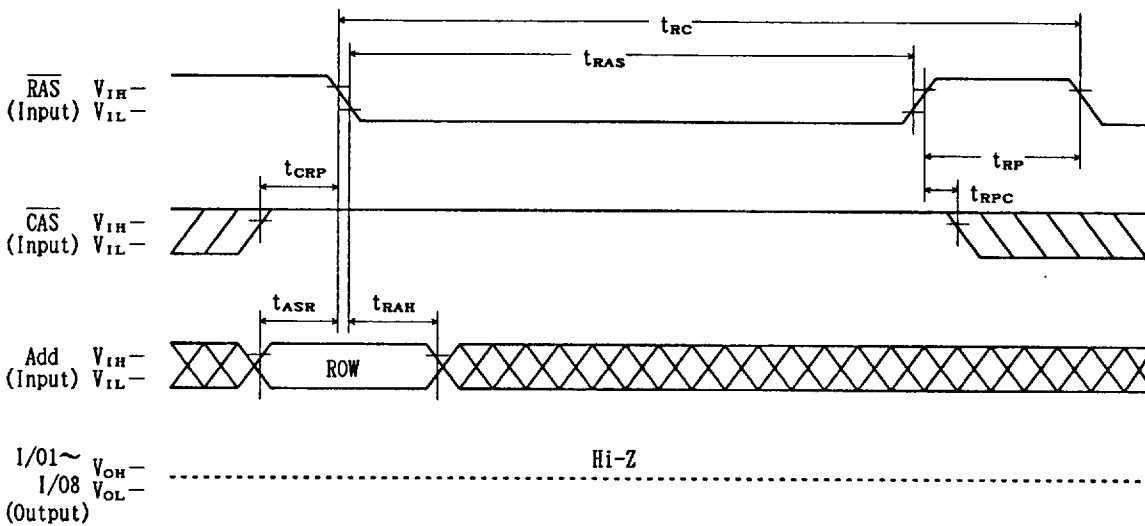
Note : $\overline{OE} = \text{Don't care}$



[illegible]

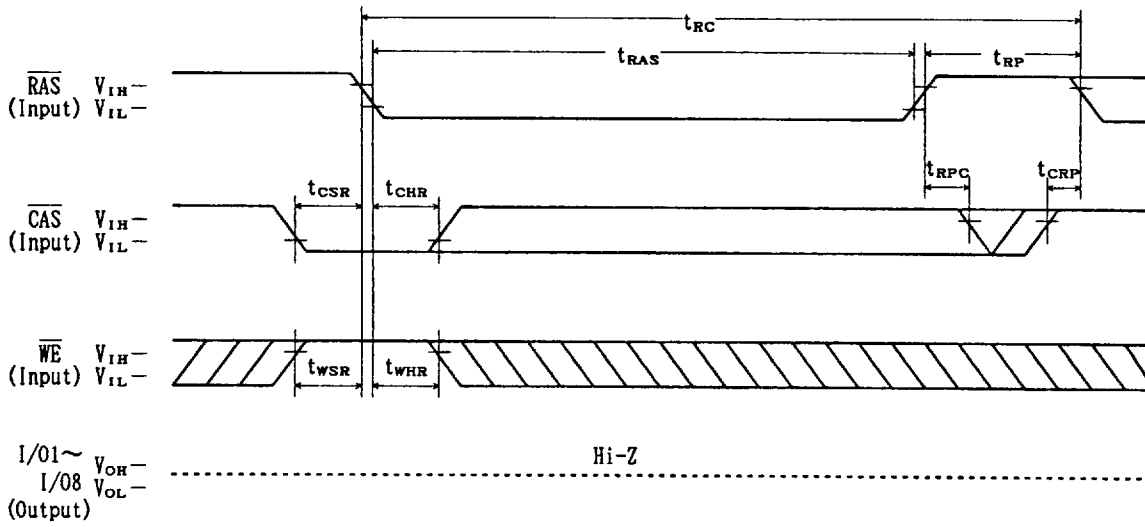
μ PD42S16800L, 42S17800L

RAS ONLY REFRESH CYCLE



Note: $\overline{WE}$, $\overline{OE}$ = Don't care

CAS BEFORE RAS REFRESH CYCLE



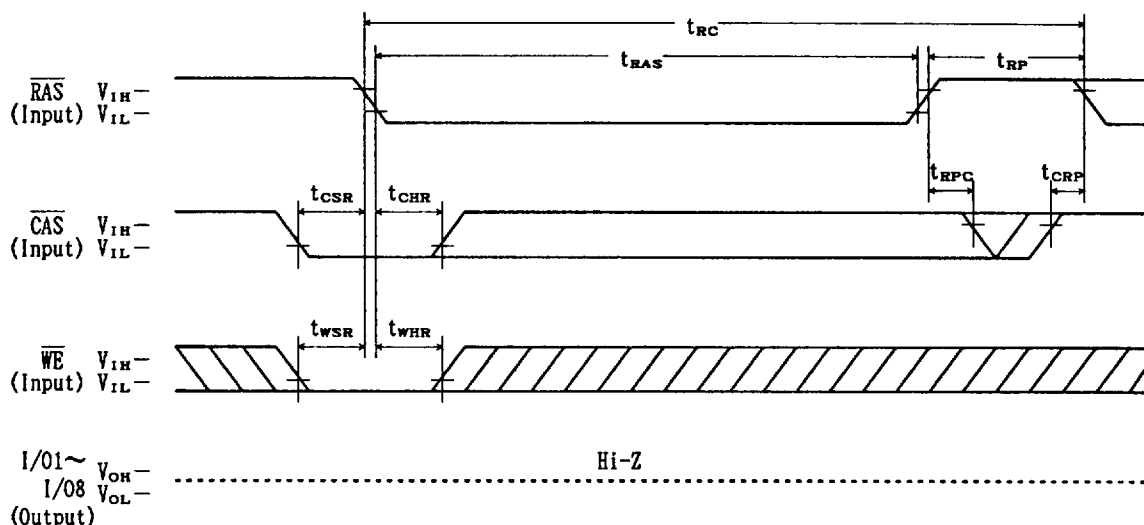
Note: $\overline{OE}$ = Don't care

Timing diagram for the 6264 16K1T1 DRAM. The diagram shows the relationship between RAS (Input), CAS (Input), WE (Input), and I/O (Output) signals. Key timing parameters are labeled: t_{RPC} (RAS to CAS setup), t_{CPN} (CAS to RAS precharge), t_{CSR} (CAS to RAS delay), t_{TRSS} (RAS to output delay), t_{RPS} (RAS to output delay), t_{CHS} (CAS to output delay), t_{WSR} (WE to output delay), t_{WHR} (WE to output delay), and t_{OPP} (output pulse width). The output signal is shown as a series of pulses with a high-impedance (Hi-Z) state.

μ PD42S16800L, 42S17800L

TEST MODE SET CYCLE

($\overline{\text{WE}}$ AND $\overline{\text{CAS}}$ BEFORE $\overline{\text{RAS}}$ REFRESH CYCLE)



TEST MODE

TEST MODE is fast test function. On using this mode, test time is reduced to 1/2.

In this TEST MODE, internal organization is 1M words by 16-bit apparently. The input levels of the CAS input A0 are Don't care.

1. How to enter into TEST MODE

Through TEST MODE SET CYCLE ($\overline{\text{WE}}$ and $\overline{\text{CAS}}$ before $\overline{\text{RAS}}$ refresh cycle), the device is entered into TEST MODE.

2. Write/Read in TEST MODE

Write data "1" or "0" through I/O1 to I/O8 by controlling address except for above-mentioned address. Each input data through each I/O (I/O1, I/O2, I/O3, I/O4, I/O5, I/O6, I/O7, I/O8) write 2 bits at once. And read through I/O1 to I/O8 to check written data.

In case of writing each 2 bits rightly, each I/O data is "1". But wrong, each I/O data is "0".

3. Refresh in TEST MODE

Use normal read cycle or $\overline{\text{WE}}$ and $\overline{\text{CAS}}$ before $\overline{\text{RAS}}$ refresh cycle.

4. How to reset TEST MODE

Through RAS only refresh cycle or $\overline{\text{CAS}}$ before $\overline{\text{RAS}}$ refresh cycle, the device is reset TEST MODE.

3. PACKAGE DRAWINGS

26 PIN PLASTIC SOJ (300mil)	24 Leads	495
28 PIN PLASTIC SOJ (400mil)	24 Leads	496
28 PIN PLASTIC SOJ (400mil)	28 Leads	497
32 PIN PLASTIC SOJ (400mil)		498
42 PIN PLASTIC SOJ (400mil)		499
26 PIN PLASTIC TSOP (300mil) *	24 Leads	500
26 PIN PLASTIC TSOP (300mil) *	24 Leads Reverse bent	501
28 PIN PLASTIC TSOP (400mil)	24 Leads	502
28 PIN PLASTIC TSOP (400mil)	24 Leads Reverse bent	503
28 PIN PLASTIC TSOP (400mil)	28 Leads	504
28 PIN PLASTIC TSOP (400mil)	28 Leads Reverse bent	505
32 PIN PLASTIC TSOP (400mil)		506
32 PIN PLASTIC TSOP (400mil)	Reverse bent	507
50 PIN PLASTIC TSOP (400mil)	44 Leads	508
50 PIN PLASTIC TSOP (400mil)	44 Leads Reverse bent	509
24 PIN PLASTIC ZIP (475mil)		510
28 PIN PLASTIC ZIP (475mil)		511
32 PIN PLASTIC ZIP (475mil)		512

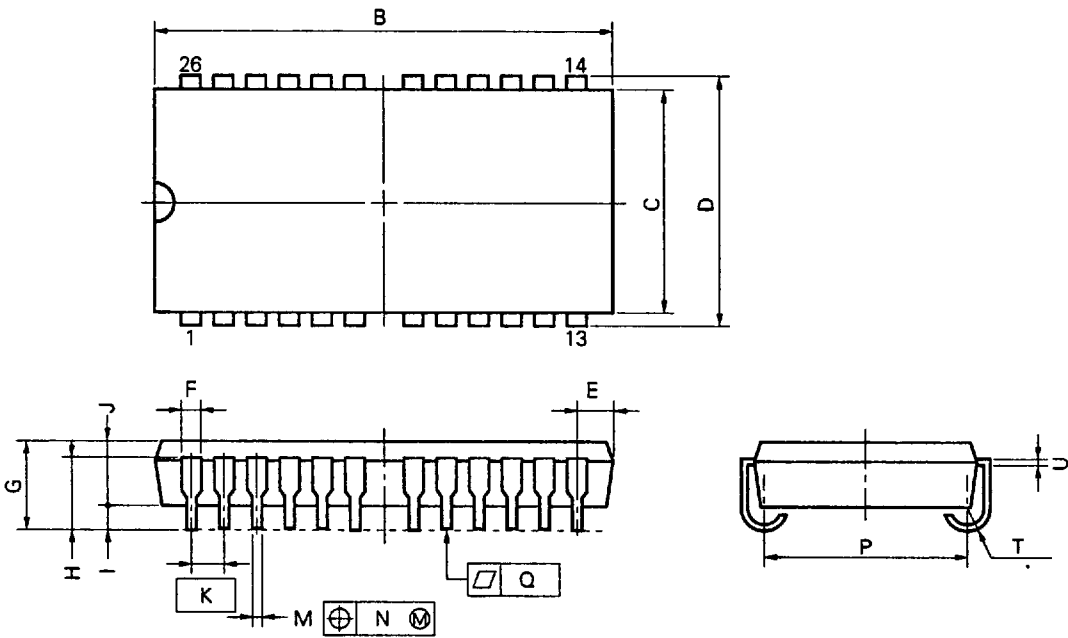
* : under development

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494

26 PIN PLASTIC SOJ (300mil)
24 Leads

NEC Cord:S26LA-300A

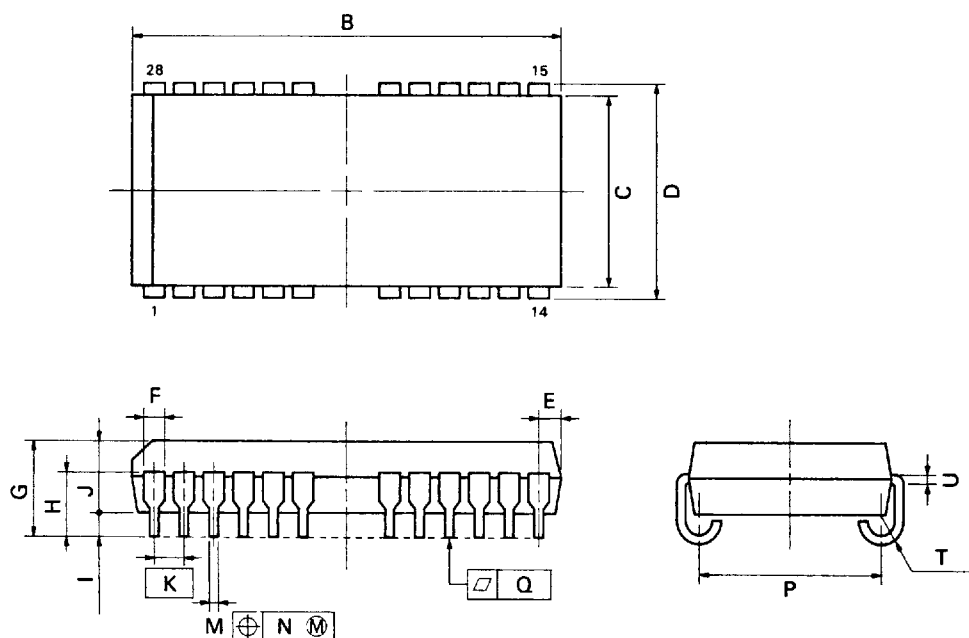


NOTE
Each lead centerline is located within 0.12 mm (0.005 inch) of its true position (T.P.) at maximum material condition.

S26LA-300A		
ITEM	MILLIMETERS	INCHES
B	17.1 ^{+0.25} _{-0.05}	0.673 ^{+0.010} _{-0.002}
C	7.62	0.300
D	8.47±0.2	0.333 ^{+0.009} _{-0.008}
E	1.03±0.15	0.041 ^{+0.006} _{-0.007}
F	0.74	0.029
G	3.5±0.2	0.138±0.008
H	2.545±0.2	0.100±0.008
I	0.8 MIN.	0.031 MIN.
J	2.6	0.102
K	1.27 (T.P.)	0.050 (T.P.)
M	0.40±0.10	0.016 ^{+0.004} _{-0.005}
N	0.12	0.005
P	6.73±0.20	0.265±0.008
Q	0.10	0.004
T	R 0.85	R 0.033
U	0.20 ^{+0.10} _{-0.05}	0.008 ^{+0.004} _{-0.002}

28 PIN PLASTIC SOJ (400mil)
24 Leads

NEC Cord:P28LE-400A



P28LE-400A

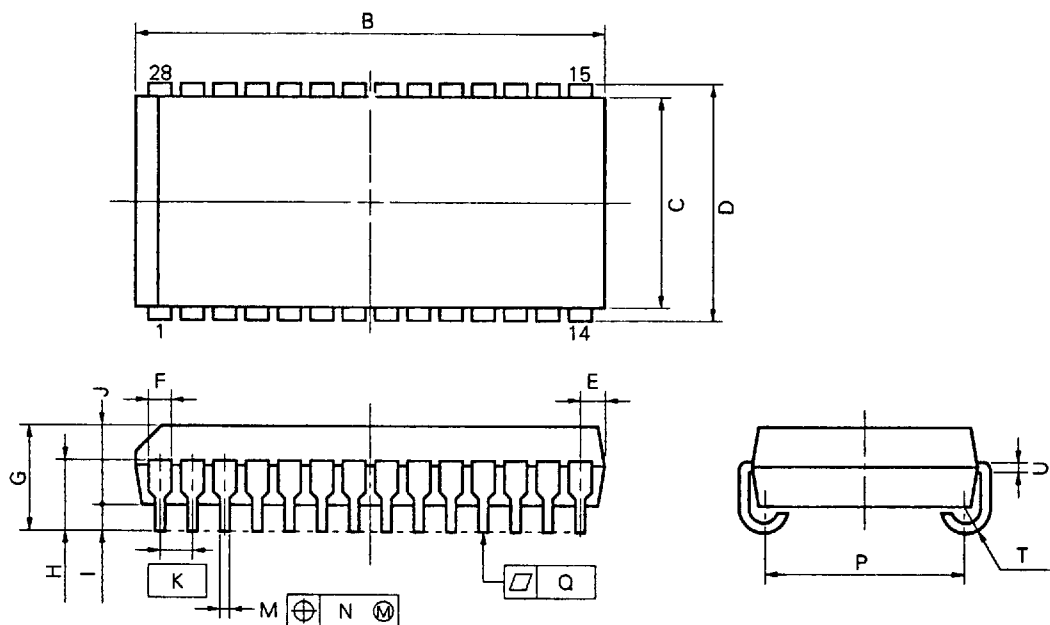
NOTE

Each lead centerline is located within 0.12 mm (0.005 inch) of its true position (T.P.) at maximum material condition.

ITEM	MILLIMETERS	INCHES
B	18.67 ^{+0.25} _{-0.35}	0.735 ^{+0.008} _{-0.013}
C	10.16	0.400
D	11.18 ^{+0.2} _{-0.2}	0.440 ^{+0.008} _{-0.007}
E	1.08 ^{+0.15} _{-0.15}	0.043 ^{+0.006} _{-0.007}
F	0.7	0.028
G	3.5 ^{+0.2} _{-0.2}	0.138 ^{+0.008} _{-0.008}
H	2.4 ^{+0.2} _{-0.2}	0.094 ^{+0.008} _{-0.008}
I	0.8 MIN.	0.031 MIN.
J	2.6	0.102
K	1.27 (T.P.)	0.050 (T.P.)
M	0.40 ^{+0.10} _{-0.10}	0.016 ^{+0.004} _{-0.004}
N	0.12	0.005
P	9.40 ^{+0.20} _{-0.20}	0.370 ^{+0.008} _{-0.007}
Q	0.15	0.006
T	R0.85	R0.033
U	0.20 ^{+0.10} _{-0.08}	0.008 ^{+0.004} _{-0.004}

28 PIN PLASTIC SOJ (400mil)
28 Leads

NEC Cord:P28LE-400A1



NOTE

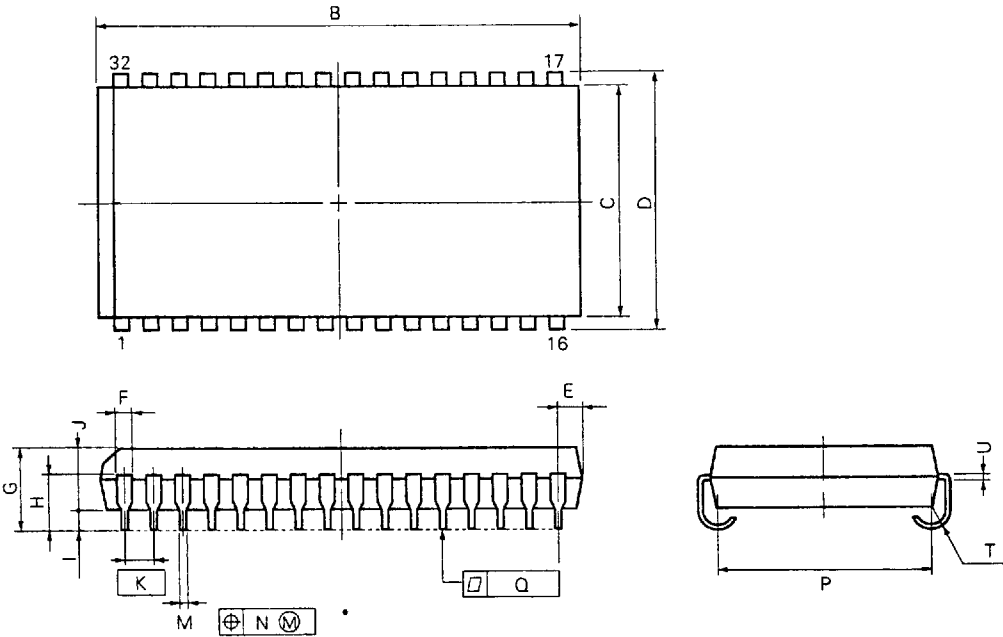
Each lead centerline is located within 0.12 mm (0.005 inch) of its true position (T.P.) at maximum material condition.

P28LE-400A1

ITEM	MILLIMETERS	INCHES
B	$18.67^{+0.2}_{-0.35}$	$0.735^{+0.008}_{-0.013}$
C	10.16	0.400
D	11.18 ± 0.2	$0.440^{+0.008}_{-0.007}$
E	1.08 ± 0.15	$0.043^{+0.006}_{-0.007}$
F	0.74	0.029
G	3.5 ± 0.2	$0.138^{+0.008}_{-0.007}$
H	2.545 ± 0.2	0.100 ± 0.008
I	0.8 MIN	0.031 MIN.
J	2.6	0.102
K	1.27 (T.P.)	0.050 (T.P.)
M	0.40 ± 0.10	$0.016^{+0.004}_{-0.005}$
N	0.12	0.005
P	9.40 ± 0.20	$0.370^{+0.008}_{-0.007}$
Q	0.10	0.004
T	R 0.85	R 0.033
U	$0.20^{+0.10}_{-0.05}$	$0.008^{+0.004}_{-0.002}$

32 PIN PLASTIC SOJ (400mil)

NEC Cord:P32LE-400A

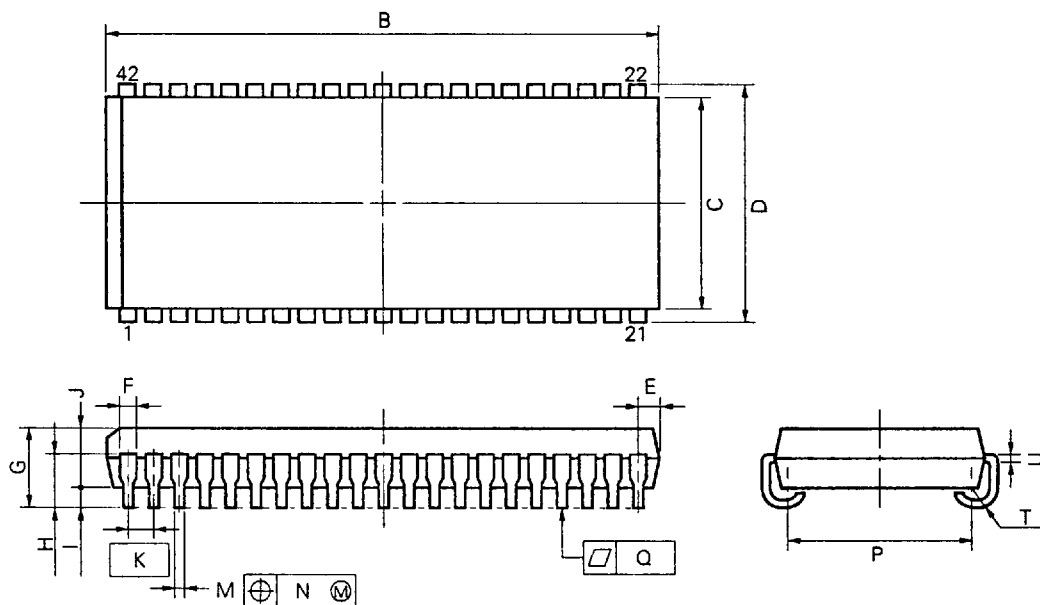


NOTE
Each lead centerline is located within 0.12 mm (0.005 inch) of its true position (T.P.) at maximum material condition

P32LE-400A		
ITEM	MILLIMETERS	INCHES
B	21.06±0.2	0.829±0.008
C	10.16	0.400
D	11.18±0.2	0.440±0.008
E	1.005±0.1	0.040 ^{+0.004} _{-0.005}
F	0.74	0.029
G	3.5±0.2	0.138±0.008
H	2.545±0.2	0.100±0.008
I	0.8 MIN	0.031 MIN
J	2.6	0.102
K	1.27 (T.P.)	0.050 (T.P.)
M	0.40±0.10	0.016 ^{+0.004} _{-0.005}
N	0.12	0.005
P	9.4±0.20	0.370±0.008
Q	0.1	0.004
T	R 0.85	R 0.033
U	0.20 ^{+0.10} _{-0.02}	0.008 ^{+0.004} _{-0.002}

42 PIN PLASTIC SOJ (400mil)

NEC Cord:P42LE-400A

**NOTE**

Each lead centerline is located within 0.12 mm (0.005 inch) of its true position (T.P.) at maximum material condition.

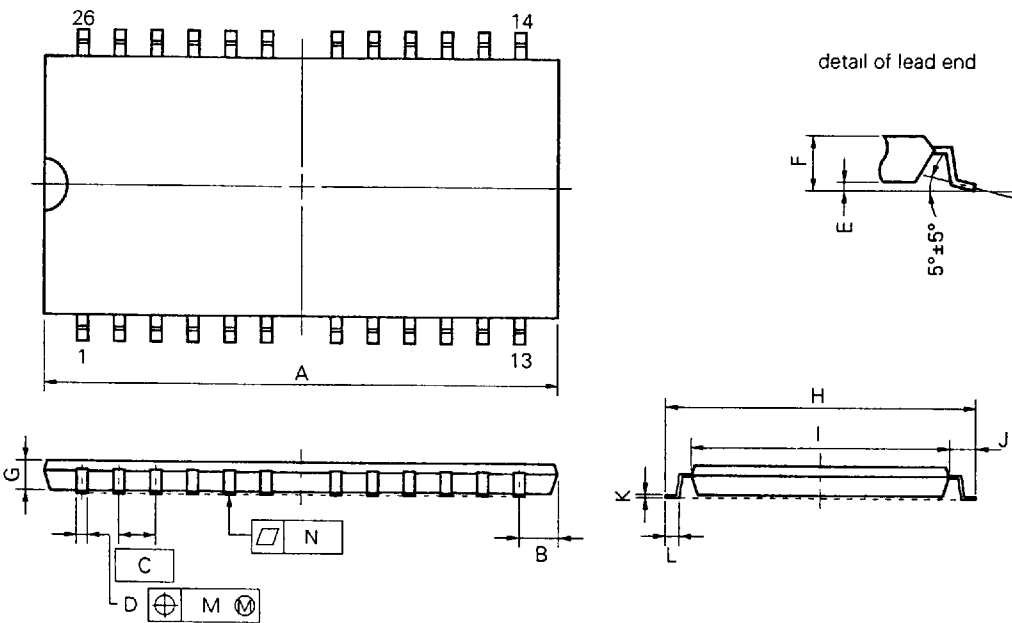
P42LE-400A

ITEM	MILLIMETERS	INCHES
B	$27.56^{+0.2}_{-0.35}$	$1.085^{+0.008}_{-0.014}$
C	10.16	0.400
D	11.18 ± 0.2	0.440 ± 0.008
E	1.08 ± 0.15	$0.043^{+0.006}_{-0.007}$
F	0.74	0.029
G	3.5 ± 0.2	0.138 ± 0.008
H	2.545 ± 0.2	0.100 ± 0.008
I	0.8 MIN.	0.031 MIN.
J	2.6	0.102
K	1.27 (T.P.)	0.050 (T.P.)
M	0.40 ± 0.10	$0.016^{+0.004}_{-0.005}$
N	0.12	0.005
P	9.4 ± 0.20	0.370 ± 0.008
Q	0.10	0.004
T	R 0.85	R 0.033
U	$0.20^{+0.10}_{-0.05}$	$0.008^{+0.004}_{-0.002}$

26 PIN PLASTIC TSOP (300mil) *
 24 Leads

* : under development

NEC Cord:S26G3-50-7JD



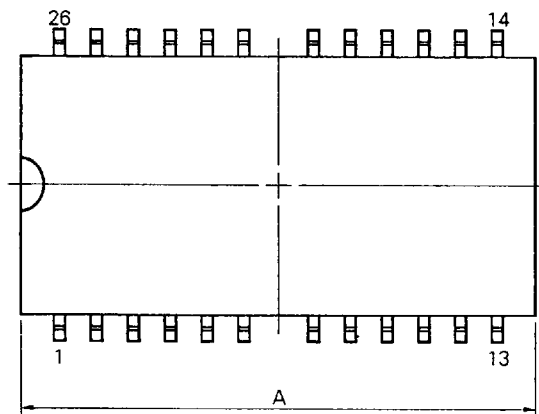
NOTE
 Each lead centerline is located within 0.21 mm (0.009 inch) of its true position (T.P.) at maximum material condition.

S26G3-50-7JD		
ITEM	MILLIMETERS	INCHES
A	17.40 MAX.	0.685 MAX.
B	1.06 MAX.	0.042 MAX.
C	1.27 (T.P.)	0.050 (T.P.)
D	0.40±0.10	0.016 ^{+0.004} _{-0.005}
E	0.05±0.05	0.002±0.002
F	1.1 MAX.	0.044 MAX.
G	0.97	0.038
H	9.22±0.2	0.363±0.008
I	7.62±0.1	0.300±0.004
J	0.8±0.2	0.031 ^{+0.009} _{-0.008}
K	0.125 ^{+0.10} _{-0.05}	0.005 ^{+0.004} _{-0.002}
L	0.5±0.1	0.020 ^{+0.004} _{-0.005}
M	0.21	0.009
N	0.10	0.004

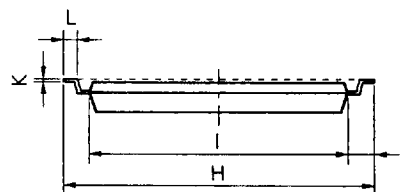
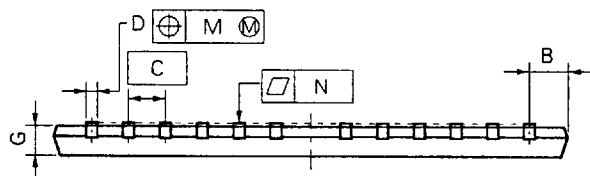
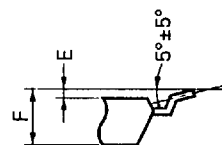
26 PIN PLASTIC TSOP (300mil) *
24 Leads Reverse bent

* : under development

NEC Cord:S26G3-50-7KD



detail of lead end



NOTE

Each lead centerline is located within 0.21 mm (0.009 inch) of its true position (T.P) at maximum material condition

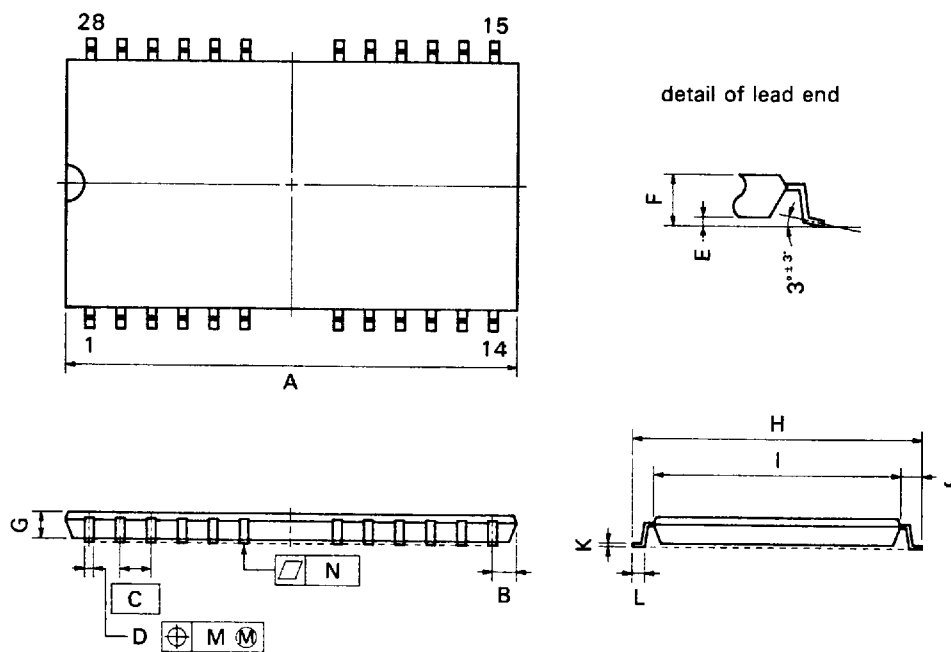
S26G3-50-7KD

ITEM	MILLIMETERS	INCHES
A	17.40 MAX.	0.685 MAX.
B	1.06 MAX.	0.042 MAX.
C	1.27 (T P)	0.050 (T.P.)
D	0.40±0.10	0.016 ^{+0.004} _{-0.005}
E	0.05±0.05	0.002±0.002
F	1.1 MAX.	0.044 MAX.
G	0.97	0.038
H	9.22±0.2	0.363±0.008
I	7.62±0.1	0.300±0.004
J	0.8±0.2	0.031 ^{+0.009} _{-0.008}
K	0.125 ^{+0.10} _{-0.05}	0.005 ^{+0.004} _{-0.002}
L	0.5±0.1	0.020 ^{+0.004} _{-0.005}
M	0.21	0.009
N	0.10	0.004

28 PIN PLASTIC TSOP (400mil)

24 Leads

NEC Cord:S28G5-50-7JD1



NOTE

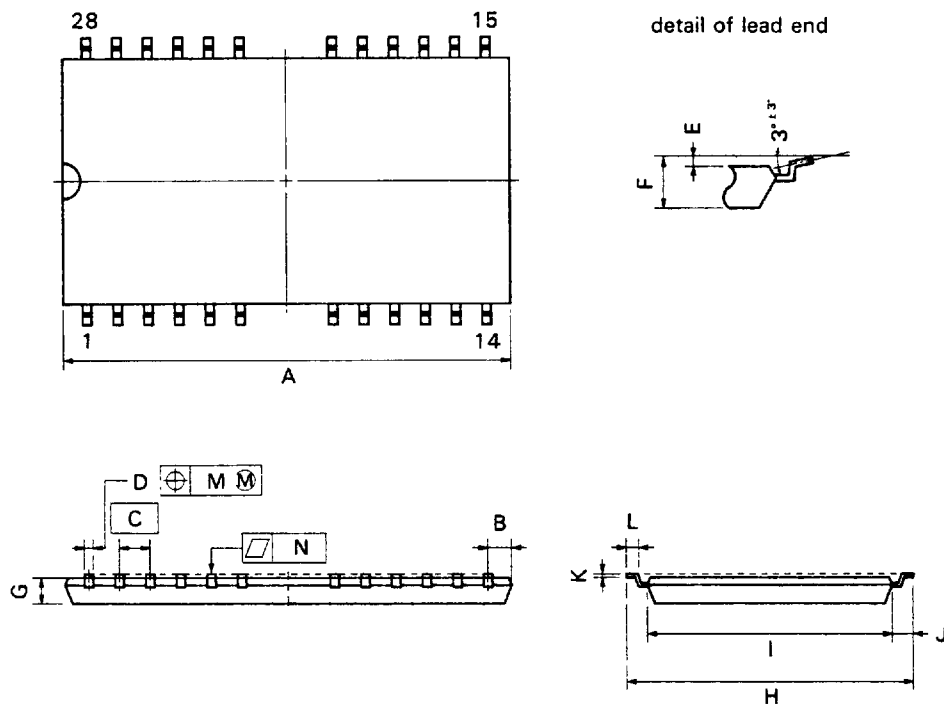
Each lead centerline is located within 0.21 mm (0.009 inch) of its true position (T.P.) at maximum material condition.

S28G5-50-7JD1

ITEM	MILLIMETERS	INCHES
A	18.81 MAX.	0.741 MAX.
B	1.15 MAX.	0.046 MAX.
C	1.27 (T.P.)	0.050 (T.P.)
D	0.40 ± 0.10	0.016 ± 0.004
E	0.05 ± 0.05	0.002 ± 0.002
F	1.1 MAX.	0.044 MAX.
G	0.97	0.038
H	11.76 ± 0.2	0.463 ± 0.008
I	10.16 ± 0.1	0.400 ± 0.004
J	0.8 ± 0.2	0.031 ± 0.008
K	0.125 ± 0.10	0.005 ± 0.004
L	0.5 ± 0.1	0.020 ± 0.004
M	0.21	0.009
N	0.10	0.004

28 PIN PLASTIC TSOP (400mil)
24 Leads Reverse bent

NEC Cord:S28G5-50-7KD1



NOTE

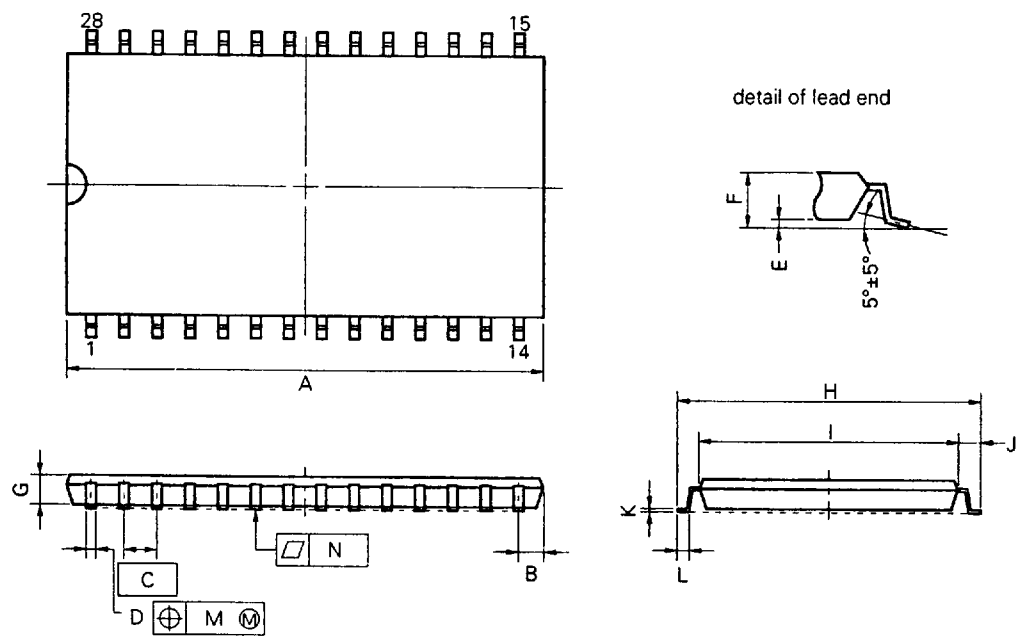
Each lead centerline is located within 0.21 mm (0.009 inch) of its true position (T.P.) at maximum material condition.

S28G5-50-7KD1

ITEM	MILLIMETERS	INCHES
A	18.81 MAX.	0.741 MAX.
B	1.15 MAX.	0.046 MAX.
C	1.27 (T.P.)	0.050 (T.P.)
D	0.40 ± 0.10	0.016 ± 0.004
E	0.05 ± 0.05	0.002 ± 0.002
F	1.1 MAX.	0.044 MAX.
G	0.97	0.038
H	11.76 ± 0.2	0.463 ± 0.008
I	10.16 ± 0.1	0.400 ± 0.004
J	0.8 ± 0.2	0.031 ± 0.008
K	0.125 ± 0.02	0.005 ± 0.001
L	0.5 ± 0.1	0.020 ± 0.004
M	0.21	0.009
N	0.10	0.004

28 PIN PLASTIC TSOP (400mil)
28 Leads

NEC Cord:S28G5-50-7JD2

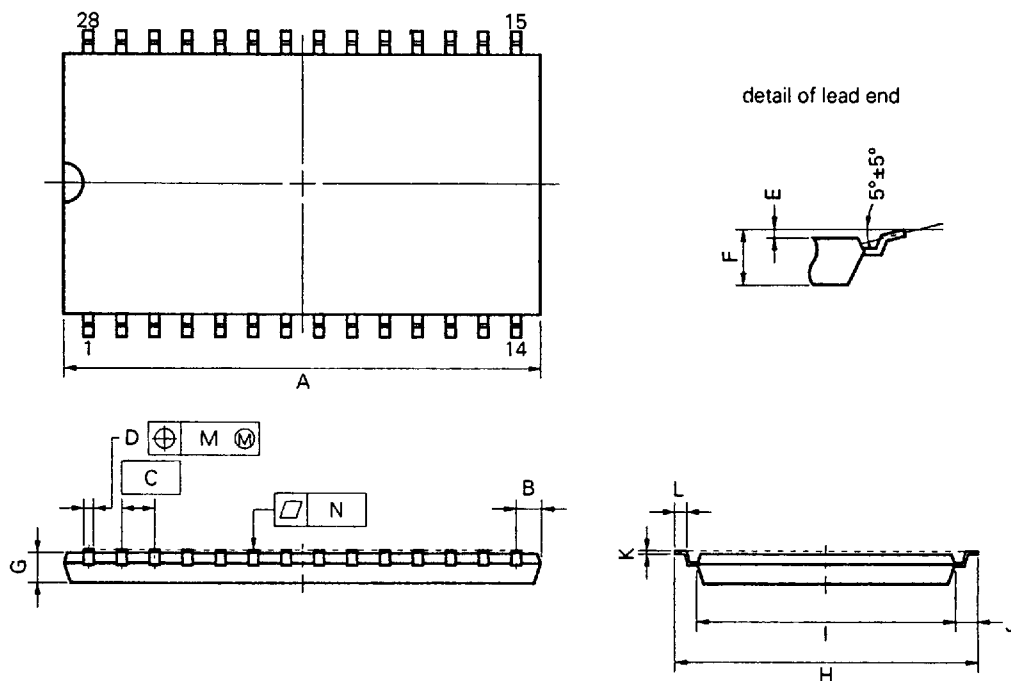


NOTE
Each lead centerline is located within 0.21 mm (0.009 inch) of its true position (T.P.) at maximum material condition.

S28G5-50-7JD2		
ITEM	MILLIMETERS	INCHES
A	18.81 MAX.	0.741 MAX.
B	1.15 MAX.	0.046 MAX.
C	1.27 (T.P.)	0.050 (T.P.)
D	0.40±0.10	0.016 ^{+0.004} _{-0.005}
E	0.05±0.05	0.002±0.002
F	1.1 MAX.	0.044 MAX.
G	0.97	0.038
H	11.76±0.2	0.463±0.008
I	10.16±0.1	0.400±0.004
J	0.8±0.2	0.031 ^{+0.009} _{-0.008}
K	0.125 ^{+0.10} _{-0.05}	0.005 ^{+0.004} _{-0.002}
L	0.5±0.15	0.020 ^{+0.006} _{-0.007}
M	0.21	0.009
N	0.10	0.004

28 PIN PLASTIC TSOP (400mil)
28 Leads Reverse bent

NEC Cord:S28G5-50-7KD2



NOTE

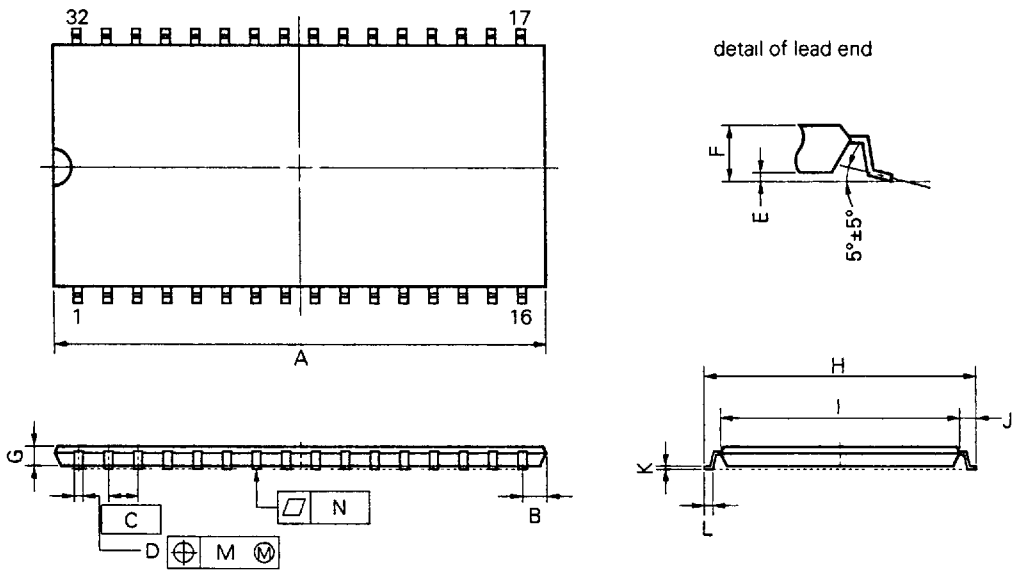
Each lead centerline is located within 0.21 mm (0.009 inch) of its true position (T.P.) at maximum material condition.

S28G5-50-7KD2

ITEM	MILLIMETERS	INCHES
A	18.81 MAX.	0.741 MAX.
B	1.15 MAX.	0.046 MAX.
C	1.27 (T.P.)	0.050 (T.P.)
D	0.40±0.10	0.016 ^{+0.004} _{-0.005}
E	0.05±0.05	0.002±0.002
F	1.1 MAX.	0.044 MAX.
G	0.97	0.038
H	11.76±0.2	0.463±0.008
I	10.16±0.1	0.400±0.004
J	0.8±0.2	0.031 ^{+0.009} _{-0.008}
K	0.125 ^{+0.10} _{-0.05}	0.005 ^{+0.004} _{-0.002}
L	0.5±0.15	0.020 ^{+0.006} _{-0.007}
M	0.21	0.009
N	0.10	0.004

32 PIN PLASTIC TSOP (400mil)

NEC Cord:S32G5-50-7JD1

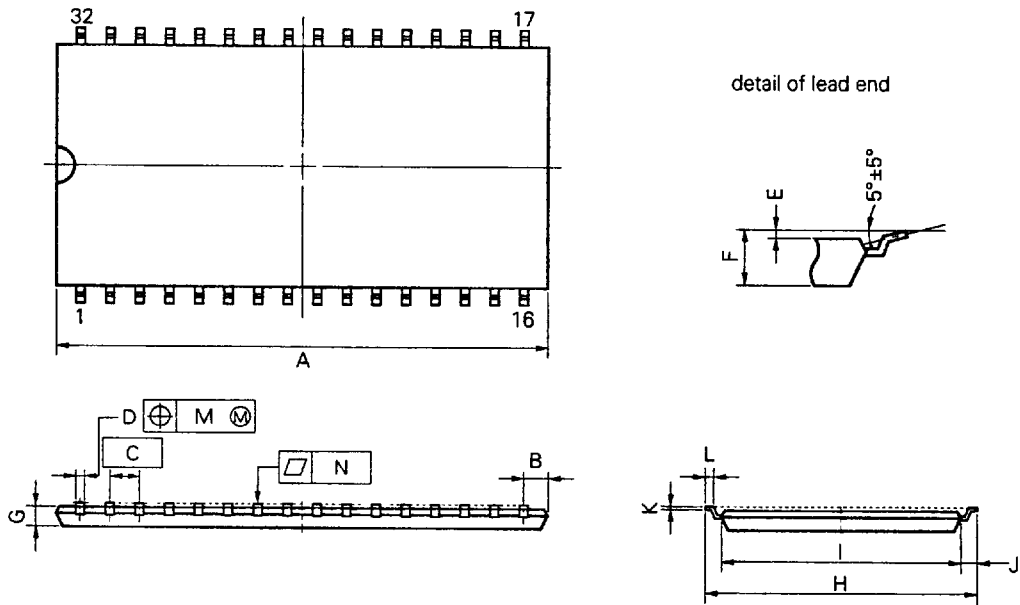


NOTE
Each lead centerline is located within 0.21 mm (0.009 inch) of its true position (T.P.) at maximum material condition.

S32G5-50-7JD1		
ITEM	MILLIMETERS	INCHES
A	21.17 MAX.	0.834 MAX.
B	1.06 MAX.	0.042 MAX.
C	1.27 (T.P.)	0.050 (T.P.)
D	0.40±0.10	0.016 ^{+0.004} _{-0.005}
E	0.05±0.05	0.002±0.002
F	1.1 MAX.	0.044 MAX.
G	0.97	0.038
H	11.76±0.2	0.463±0.008
I	10.16±0.1	0.400±0.004
J	0.8±0.2	0.031 ^{+0.009} _{-0.008}
K	0.125 ^{+0.10} _{-0.05}	0.005 ^{+0.004} _{-0.002}
L	0.5±0.15	0.020 ^{+0.006} _{-0.007}
M	0.21	0.009
N	0.10	0.004

32 PIN PLASTIC TSOP (400mil)
Reverse bent

NEC Cord:S32G5-50-7KD1



NOTE

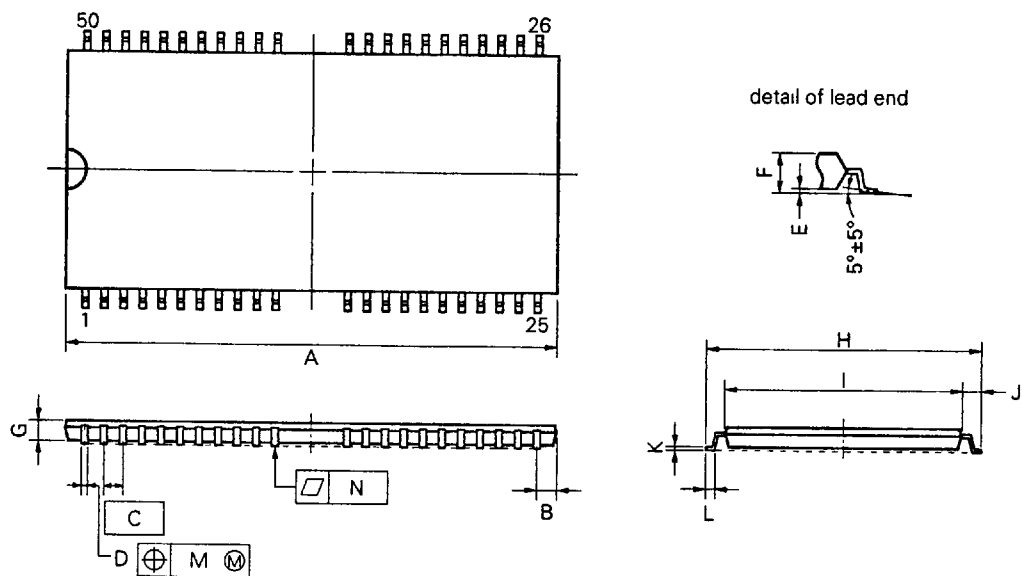
Each lead centerline is located within 0.21 mm (0.009 inch) of its true position (T.P.) at maximum material condition.

S32G5-50-7KD1

ITEM	MILLIMETERS	INCHES
A	21.17 MAX.	0.834 MAX.
B	1.06 MAX.	0.042 MAX.
C	1.27 (T.P.)	0.050 (T.P.)
D	0.40±0.10	0.016 ^{+0.004} _{-0.005}
E	0.05±0.05	0.002±0.002
F	1.1 MAX.	0.044 MAX.
G	0.97	0.038
H	11.76±0.2	0.463±0.008
I	10.16±0.1	0.400±0.004
J	0.8±0.2	0.031 ^{+0.009} _{-0.008}
K	0.125 ^{+0.10} _{-0.05}	0.005 ^{+0.004} _{-0.002}
L	0.5±0.15	0.020 ^{+0.006} _{-0.007}
M	0.21	0.009
N	0.10	0.004

50 PIN PLASTIC TSOP (400mil)
44 Leads

NEC Cord:S50G5-80-7JF



NOTE

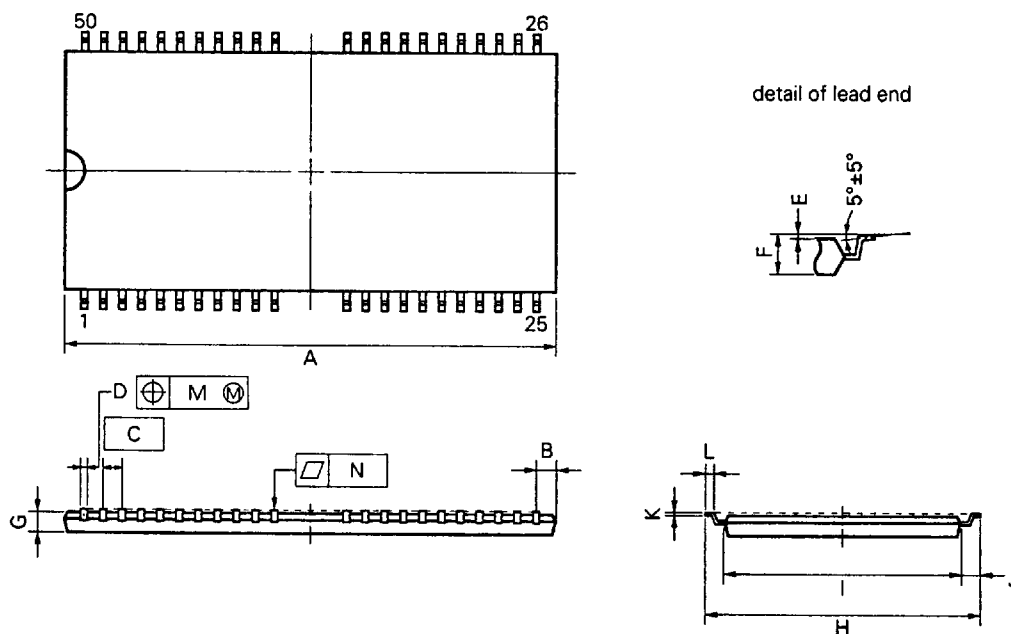
Each lead centerline is located within 0.13 mm (0.005 inch) of its true position (T.P.) at maximum material condition.

S50G5-80-7JF

ITEM	MILLIMETERS	INCHES
A	21.45 MAX.	0.845 MAX.
B	1.13 MAX.	0.045 MAX.
C	0.8 (T.P.)	0.031 (T.P.)
D	0.30±0.10	0.012 ^{+0.004} _{-0.005}
E	0.05±0.05	0.002±0.002
F	1.1 MAX.	0.044 MAX.
G	0.97	0.038
H	11.76±0.2	0.463±0.008
I	10.16±0.1	0.400±0.004
J	0.8±0.2	0.031 ^{+0.009} _{-0.008}
K	0.125 ^{+0.10} _{-0.05}	0.005 ^{+0.004} _{-0.002}
L	0.5±0.15	0.020 ^{+0.006} _{-0.007}
M	0.13	0.005
N	0.10	0.004

50 PIN PLASTIC TSOP (400mil)
44 Leads Reverse bent

NEC Cord:S50G5-80-7KF

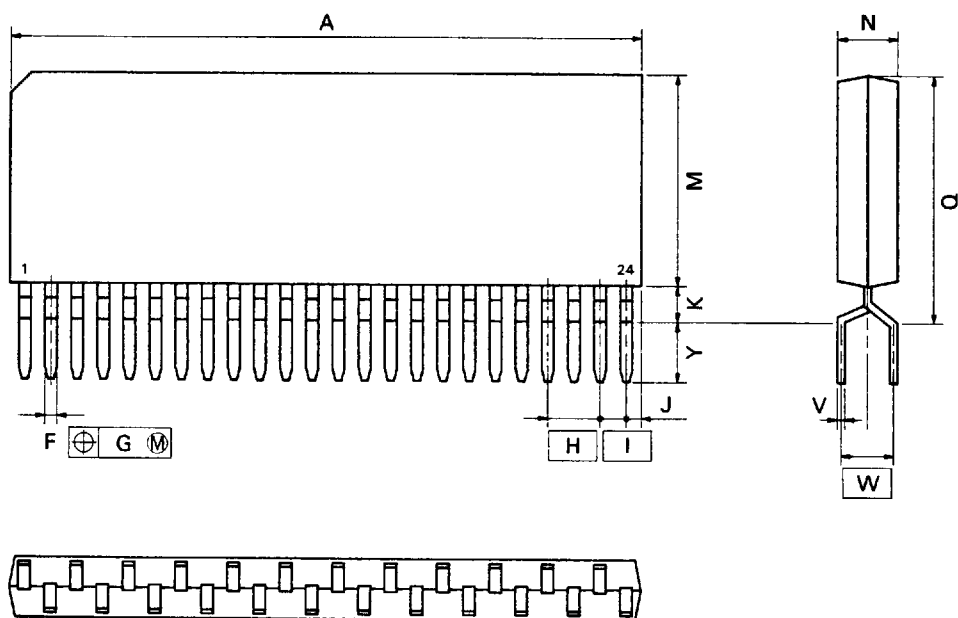


S50G5-80-7KF

ITEM	MILLIMETERS	INCHES
A	21.45 MAX.	0.845 MAX.
B	1.13 MAX.	0.045 MAX.
C	0.8 (T.P.)	0.031 (T.P.)
D	0.30±0.10	0.012 ^{+0.004} _{-0.005}
E	0.05±0.05	0.002±0.002
F	1.1 MAX.	0.044 MAX.
G	0.97	0.038
H	11.76±0.2	0.463±0.008
I	10.16±0.1	0.400±0.004
J	0.8±0.2	0.031 ^{+0.009} _{-0.008}
K	0.125 ^{+0.10} _{-0.05}	0.005 ^{+0.004} _{-0.002}
L	0.5±0.15	0.020 ^{+0.006} _{-0.007}
M	0.13	0.005
N	0.10	0.004

24 PIN PLASTIC ZIP (475mil)

NEC Cord:P24V-100-475A



P24V-100-475A

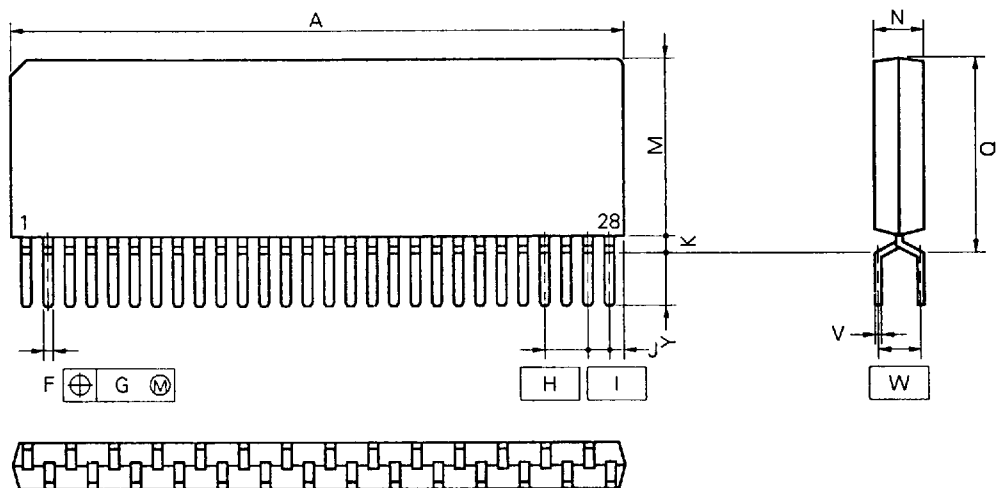
NOTE

Each lead centerline is located within 0.25 mm (0.010 inch) of its true position (T.P.) at maximum material condition.

ITEM	MILLIMETERS	INCHES
A	31.75 MAX.	1.250 MAX.
F	0.50 ± 0.1	0.020 ± 0.004
G	$\phi 0.25$	$\phi 0.010$
H	2.54	0.100
I	1.27	0.050
J	1.27 MAX.	0.050 MAX.
K	1.0 MIN.	0.039 MIN.
M	10.8 MAX.	0.426 MAX.
N	2.8 ± 0.2	0.110 ± 0.008
Q	12.07 MAX.	0.476 MAX.
V	0.25 ± 0.10	0.010 ± 0.004
W	2.54	0.100
Y	3.3 ± 0.5	0.130 ± 0.02

28 PIN PLASTIC ZIP (475mil)

NEC Cord:P28VF-100-475A



NOTE

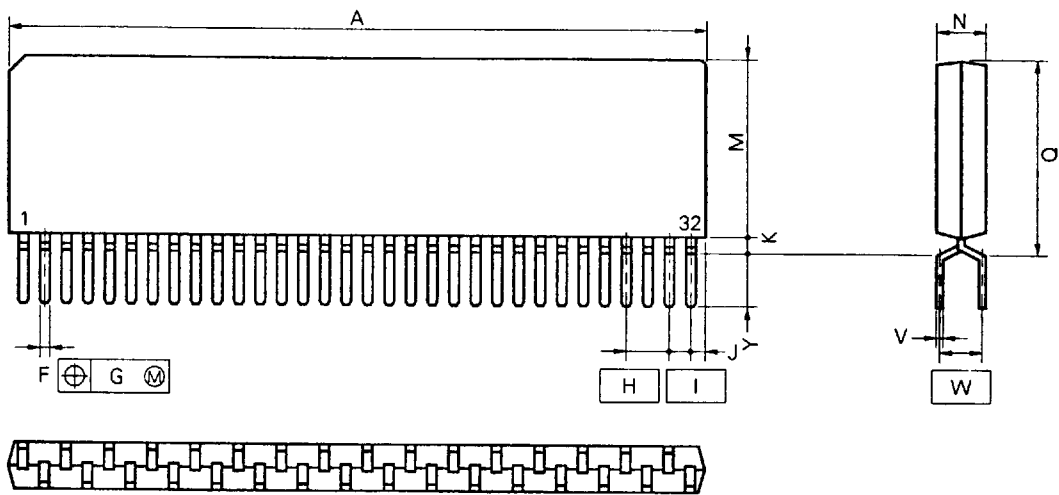
Each lead centerline is located within 0.25 mm (0.010 inch) of its true position (T.P.) at maximum material condition.

P28VF-100-475A

ITEM	MILLIMETERS	INCHES
A	36.83 MAX.	1.450 MAX.
F	0.5±0.10	0.020 ^{+0.004} _{-0.005}
G	0.25	0.010
H	2.54 (T.P.)	0.100 (T.P.)
I	1.27 (T.P.)	0.050 (T.P.)
J	1.27 MAX.	0.050 MAX.
K	0.9 MIN.	0.035 MIN.
M	10.8 MAX.	0.426 MAX.
N	2.8±0.2	0.110 ^{+0.009} _{-0.008}
Q	12.07 MAX.	0.475 MAX.
V	0.25 ^{+0.10} _{-0.05}	0.010 ^{+0.004} _{-0.003}
W	2.54 (T.P.)	0.100 (T.P.)
Y	3.25±0.2	0.128±0.008

32 PIN PLASTIC ZIP (475mil)

NEC Cord:P32VF-100-475A



NOTE
Each lead centerline is located within 0.25 mm (0.010 inch) of its true position (T.P.) at maximum material condition.

P32VF-100-475A		
ITEM	MILLIMETERS	INCHES
A	41.91 MAX.	1.650 MAX
F	0.5±0.10	0.020 ^{+0.004} _{-0.005}
G	0.25	0.010
H	2.54 (T.P.)	0.100 (T.P.)
I	1.27 (T.P.)	0.050 (T.P.)
J	1.27 MAX.	0.050 MAX.
K	0.9 MIN.	0.035 MIN.
M	10.8 MAX.	0.426 MAX.
N	2.8±0.2	0.110 ^{+0.009} _{-0.008}
Q	12.07 MAX.	0.475 MAX.
V	0.25 ^{+0.10} _{-0.05}	0.010 ^{+0.004} _{-0.003}
W	2.54 (T.P.)	0.100 (T.P.)
Y	3.25±0.2	0.128±0.008